

Intel® Quark™ microcontroller D2000

Datasheet

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Revision History

The Intel® Quark™ microcontroller D2000 is an ultra-low power Intel Architecture (IA) SoC that integrates an Intel® Quark processor core, Memory Subsystem with ondie volatile and non-volatile storage, and I/O interfaces into a single low-cost systemon-chip solution.

[Figure](#page-15-1) 1 shows the system level block diagram of the SoC. Refer to the subsequent chapters for detailed information on the individual functional blocks.

Figure 1. SoC Block Diagram

1.1 Feature Overview

1.1.1 Clock Oscillators

- • 32 MHz Clock (system clock) generated by on-die Hybrid Oscillator which works in either:
	- o Silicon mode (external crystal not needed) (generates 4/8/16/32 MHz clock output as configured) or
	- o Crystal mode (external 32MHz crystal required).
- • 32.768 kHz RTC Clock generated by on-die RTC Crystal oscillator (external 32.768kHz crystal required). SoC is designed to work without RTC clock, if there is no use-case for RTC clock.

1.1.2 Quark Processor Core

- 32 MHz Clock Frequency
- 32-bit Address Bus
• Pentium 586 ISA Co
- Pentium 586 ISA Compatible without x87 Floating Point Unit
- Integrated Local APIC and I/O APIC
- • 1 32-bit timer in Local APIC running with system/core clock

1.1.3 Memory Subsystem

- 32 KB of 64b wide on-die Flash
- Supports Page Erase and Program cycles
- Supports configurable wait states to allow Flash to run at various frequencies. At 32MHz, 2-wait-states are introduced for all accesses
- 4 configurable Protection regions for Flash access control
- 8 KB Code OTP with independent read-disable of the two 4KB regions
- 4 KB Data OTP (One-time-programmable) memory
- 8 KB of on-die SRAM with 64b interface with 0-wait state in case of no arbitration conflict
- • 4 configurable Protection regions for SRAM access control

1.1.4 I2C

- One I²C Interface
- Three I2C speeds supported : Standard Mode (100 Kbps), Fast Mode (400 Kbps) and Fast Mode Plus (1 Mbps)
- 7-bit and 10-bit Addressing Modes Supported
- Supports Master or Slave operation
- FIFO mode support (16B TX and RX FIFO's)
- • Supports HW DMA with configurable FIFO thresholds

1.1.5 UART

- Two 16550 compliant UART interfaces
- Supports baud rates from 300 to 2M with less than 2% frequency error
- Support for hardware and software flow control
- FIFO mode support (16B TX and RX FIFO's)

- Supports HW DMA with configurable FIFO thresholds
- Supports 9-bit serial operation mode
- Supports RS485
- • Support for DTR/DCD/DSR/RI Modem Control Pins through GPIO pins controlled by Software

1.1.6 SPI

- One SPI Master Interfaces with support for SPI clock frequencies up to 16 MHz
- One SPI Slave Interface with support for SPI clock frequencies up to 3.2 MHz
- Support for 4-bit up to 32-bit Frame Size
- Up to four Slave Select pins per Master interface
- FIFO mode support (Independent 32B TX and RX FIFO's)
- • Supports HW DMA with configurable FIFO thresholds

1.1.7 DMA Controller

- Provides 2 Unidirectional Channels
- Provides support for 16 HW Handshake Interfaces
	- o tx and rx channels of I2C controller, SPI Slave controller, SPI Master controller, two UART controllers use this interface
- Supports Memory to Memory, Peripheral to Memory, Memory to Peripheral and Peripheral to Peripheral transfers
- Dedicated Hardware Handshaking interfaces with peripherals plus Software Handshaking Support
- • Supports Single and Multi-Block Transfers

1.1.8 GPIO Controller

- Provides 25 independently configurable GPIO
- All GPIOs are interrupt capable supporting level sensitive and edge triggered modes
- Debounce logic for interrupt source
- • All 25 GPIOs are Always-on interrupt and wake capable

1.1.9 Timers

- Two 32-bit Timers running at system clock (running in timer mode or PWM mode)
- Supports an additional 32-bit Always-On Counter running with 32.768 kHz clock
- • Supports an additional 32-bit Always-On Periodic Timer running with 32.768 kHz clock and with interrupt and wake capability

1.1.10 Pulse Width Modulation (PWM)

• Two 32-bit Timers running at system clock can be configured to generate two PWM outputs

1.1.11 Watchdog Timer

• Configurable Watchdog timer with support to trigger an interrupt and/or a system reset upon timeout

1.1.12 Real Time Clock (RTC)

- 32-bit Counter running from 1Hz up to 32.768 kHz
- Supports interrupt and wake event generation upon match of programmed value
- • Only requires 32.768 kHz clock to be running to generate interrupt and wake events

1.1.13 Analog to Digital Convertor (ADC)

- 19 Analog Input channels
- Selectable 6/8/10/12-bit resolution
- Supports maximum of 2.28 Mega Samples Per Second (MSps) at 12-bit resolution and 4 MSps at 6-bit resolution)
- Differential Non-Linearity DNL of +/- 1.0 LSB
- Integral Non-Linearity INL of +/- 2.0 LSB
- SINAD of 68 dBFS
- Offset Error of +/- 2 LSB (calibration enabled), +/- 64 LSB (calibration disabled)
- • Full-scale input range of 0 to AVDD.

1.1.14 Analog Comparators

- Provides 19 Analog Comparators
- Six high performance comparators
- 13 low power comparators
- Configurable polarity
- • Interrupt and Wake Event capable

1.1.15 Interrupt Routing

- Configurable Routing of SoC Interrupts with capability to route to the Interrupt Controller of the Quark Processor.
- SoC events can be routed as: Interrupts to the Quark Processor, debug break events to the Quark Processor or SoC Warm Reset requests.

1.1.16 Power Management

- • SoC System States : RUN, Low Power Compute, HALT, Low Power Wait, Deep Sleep (RTC or NORTC) state.
- Processor States : CO C2
- Supports Coin-cell Battery source (2.0V to 3.6V range)

1.1.17 Package

40-pin Quad Flat No-Leads (QFN) package.

§

2 Physical Interfaces

2.1 Pin States Through Reset

All functional IOs will come up in input mode after reset except JTAG TDO output which is kept tristated.

All Digital IO include a configurable pullup (49K ohm typ; 34K-74Kohm range) with pull-up disabled by default, except for F_20, F_22, F_23 pins (TRST_N, TMS, TDI)) where pull-up is enabled by default.

The state of all IOs is retained whenever SoC goes into low power states.

2.2 *External* **Interface Signals**

The following table gives the definition of external interface signals of Intel® Quark™ microcontroller D2000. Not all interfaces are available simultaneously through external pins of Intel® Quark™ microcontroller D2000. For pin multiplexing options, refer to [Chapter 3.](#page-27-1)

Table 1. List of User Mode External Interfaces

2.3 GPIO Multiplexing

Not all interfaces can be active at the same time. To provide flexibility, these shared interfaces are multiplexed with GPIOs.

Note: All 25 functional IOs come up as Function 0 at boot. JTAG is default enabled (as part of Function 0) instead of GPIO[23:19]. FW is responsible for enabling proper configuration later on.

Table 2. Multiplexed Functions

3 Ballout and Package Information

The Intel® Quark™ microcontroller D2000 comes in 6 mm x 6 mm Quad Flat No-Leads (QFN) Package.

3.1 SoC Attributes

- Package parameters: 6 mm X 6 mm (QFN)
- Ball Count: 40

All Units: mm

Tolerances if not specified:

- $.X: \pm 0.1$
- $.XX: \pm 0.05$
- Angles: \pm 1.0 degrees

3.2 Package Diagrams

Figure 2. Package Diagram QFN 40 pin (0.5mm pitch)

3.3 Pin Multiplexing

There are 15 dedicated pins + 1 QFN GND plane and 25 functional pins which can be configured as GPIO (GPIO[24:0]) or other functions (I2C/UART/SPI/JTAG). There are two major IO modes: user mode and test mode. In user mode, each pin can be individually configured in one of the 4 user modes (FUNC 0/1/2/3). By default, after power-on-reset (RST_N) or cold reset, SoC comes up in user mode 0 function (FUNC0). SOC firmware/software is responsible for enabling the platform specific configuration by programming the respective IO pad control registers.

Out of 25 functional pins, 19 pins are double bonded to Analog input pads and digital pads while 6 pins are digital only pads. All analog pads (AI[18:0]) are specified with respect to AVDD and all digital pads are with respect to IOVDD. The analog inputs (AI) are connected to ADC or Comparators inside the SoC. AI[5:0] is connected to fast response/high performance comparator / fast channel of ADC; and AI[18:6] are connected to slow response/low power comparator / slow channel of ADC. Any wake capable analog inputs shall be connected only to any of $AI[18:6]$ and not to $AI[5:0]$.

Table 3. Pin Multiplexing

Ballout and Package Information

All Analog IOs (AI[18:0]/ADC[18:0]) are with respect to AVDD rail.

All Digital IOs are 3.3V tolerant.

All Digital IO include configurable drive strength namely low-drive (12 mA) and highdrive (16 mA) modes. By default, all digital IOs come up in low-drive mode.

All Digital IO include a configurable pullup with pull-up disabled by default, except for F_20, F_22, F_23 (TRST_N, TMS, TDI)) where pull-up is enabled by default.

UART_A/B_CTS (input) or UART_A/B_RE (output) is available based on UART mode of operation (RS232 or RS485) configurable in respective UART controller. Similarly for UART_A/B_RTS (output) or UART_A/B_DE (output). Default is RS232. FW can choose to enable both input and output direction for CTS/RE pins and hardware will control the output enable of these pins based on RS232 or RS485 mode of operation if these pins are configured for UART function.

JTAG interface is default enabled (user mode 0) to assist in debug as well as embedded flash programming.

There is a F_25 pad which is not bonded to any pin. This pad (mapped as pin 25 for pinmux configuration in System Control Subsystem) shall be configured by FW in input disabled mode (Input Enable = 0; User mode 3 which makes Output Enable disabled).

DVDD_2 and DVDD are identical and are to be connected to the same source.

3.4 Alphabetical Ball Listing

[Table](#page-32-1) 4 shows pins arranged in increasing order of pin number.

Table 4. Pins Listed in increasing Order of Pin Number

Ballout and Package Information

3.5 Platform Requirements

3.5.1 3.5.1 Internal Voltage Regulator

Figure 4. Internal Voltage Regulator

The requirement for external component at PCB level is as shown in the table:

ESR rating for Cin and Cout:

For Cout: $Res(TYP) = 100mOhm / Resr(MAX) = 500mOhm$

For Cin: $Resr(TYP) = 25mOhm / Resr(MAX) = 100mOhm$

Please note for Cout, the higher ESR is, the higher the ripple is.

DCR rating for on-board inductor

L: $DCR(TYP) = 100mOhm$, $DCR(MAX) = 500mOhm$

The DCR impacts the efficiency of the regulator. The higher the DCR is, the lower the efficiency is.

Also, the voltage drop across the DCR increases the min dropout the regulator can support. For example, the minimum dropout specified in the spec is 200mV (Table 11) by considering a 0.1 Ohm DCR. If the DCR is higher, the dropout will also be higher.

For example, DCR=0.5 Ohm = $0.1 + 0.5$. For a 50 mA current, the dropout is 20 mV higher (0.4 Ohm*50mA).

Table 5. Parasitic Requirement for Voltage Regulator Pins

When internal voltage regulator is disabled (VR_EN = 0), PVDD must be powered up, GNDSENSE and AVS must be grounded. LX is HIZ, VSENSE to be grounded.

3.5.2 RTC Oscillator

For 32.768 kHz RTC Oscillator, refer to <http://www.murata.com/products/timingdevice/crystalu/technical/notice> for PCB guidelines.

Load capacitor on XTAL pins are integrated inside the chip but they are not adjustable. A nominal value of 11 pF is on each pin (range: 6 pF minimum and 17 pF maximum).

If there is no RTC Oscillator need, then a platform need not mount RTC XTAL on board and keep RTC_XTAL1, RTC_XTAL0 pins grounded.

3.5.3 Hybrid Oscillator

Hybrid oscillator can work in internal Silicon RC oscillator mode with +/- 2% accuracy (after trimming). If a system does not require higher accuracy system clock, then HYBOSC 32MHz XTAL need not be mounted on board to save cost and in such case, keep HYB_XTAL1, HYB_XTAL0 pins as no-connect (floating).

A programmable capacitive load can be added on the crystal terminals internal to the chip to fine tune the crystal frequency. The range and step size will vary depending on external load, process corners and crystal parameters. Load capacitance is adjustable through SCSS register in SoC (OSC0_CFG1.OSC0_FADJ_XTAL[3:0] register – range supported is 5.55 pF to 15.03 pF with default value of 10pF).

3.5.4 ADC

A simple filter is recommended to be put on board on Analog Inputs [19:0] connected to ADC, to reduce external noise. It should be understood that any additional frequency signals within the band of interest will be present in the output spectrum contributing for a performance impact. Additionally the input signal is disturbed by the fast transients due to the fast charging of the ADC input capacitor during the start of the sampling period. These transients should vanish quite rapidly and the voltage across the ADC input capacitance should reach a steady state very fast. Nevertheless in case the ADC input network is not correctly terminated these transients can travel back and forth through the input line between the ADC driver and ADC input generating a ringing. This will lead to an incorrect sampling of input signal.

A recommended input scheme to prevent this possible consequence can be

- 50 ohm resistor (in ADC side). The resistor level should match the characteristic impedance of PCB trace;
- 470pF capacitor to ground (in ADC driver side);

In order that they are effective, resistor and capacitor must be connected very close to each other and placed towards the ADC Analog input (SoC side), as follows:

Power supply decoupling on AVDD rail input shall be done with 1uF || 10 nF decoupling capacitors. The 10 nF capacitor shall be ceramic (good quality) and must be placed as close as possible to the SoC.

4 Electrical Characteristics

4.1 Thermal Specifications

Ambient temperature = -40° c to $+85^{\circ}$ c.

4.2 Voltage and Current Specifications

4.2.1 Absolute Maximum Ratings

Table 6: Absolute Maximum Voltage Ratings

Refer to Power Management chapter on voltage rail sequencing in internal voltage regulator mode and external voltage regulator mode.

4.3 Crystal Specifications

For Hybrid oscillator:

Table 7: 32MHz Crystal Oscillator specification

Table 8: 32kHz Crystal Oscillator specification

Electrical Characteristics

4.4 DC Specifications

4.4.1 IO DC specifications

FOR IOVDD=1.8V:

4.4.2 Undershoot Voltage Support

SoC supports a undershoot voltage of 300 mV (VIL min of -0.3V) on its input pins.

4.4.3 ADC IO DC characteristics

4.5 System Power Consumption

The data is preliminary and subject to revision in future.

4.6 AC Specifications

4.6.1 SPI Master IO AC characteristics

SPI Master interface consists of:

- Outputs SPI_M_SCLK, SPI_M_TXD, SPI_M_SS[3:0]
- Inputs SPI_M_RXD

The interface is timed with respect to SPI_M_SCLK which is output from SoC. A given signal is launched with respect of a configured edge and sampled with respect to the opposite edge. Thus it is a half-cycle setup/hold path.

Output load supported for SPI_M_TXD, SPI_M_SS[3:0], SPI_M_SCLK outputs is 25 pF max to support max rate of 16 Mbps.

4.6.2 SPI Slave IO AC characteristics

SPI Slave interface consists of:

- Outputs SPI_S_SDOUT
- Inputs SPI_S_SCLK, SPI_S_SDIN, SPI_S_SCS

As per SPI protocol, the interface is timed with respect to SPI_S_SCLK which is input to SoC. A given signal is launched with respect of a configured edge and sampled with respect to the opposite edge. Thus it is a half-cycle setup/hold path.

Output load supported for SPI_S_SDOUT output is 50 pF max and 5 pF min.

4.6.3 I2C Master/Slave IO AC characteristics

I2C interface consists of I2C_SCL and I2C_SDA bidirectional IOs and can operate in either master or slave mode. It can operate in standard mode (with data rates 0 to 100 Kbps), fast mode (with data rates less than or equal to 400 Kbps) or fast mode plus (with data rates less than or equal to 1 Mbps). To support fast mode plus, i2c_m0_clk (= system clock) shall be greater than or equal to 32 MHz.

I2C specification dictates timing relationship between I2C_SCL and I2C_SDA to be met, which will be broadly taken care by the I²C controller using configuration registers. SoC complies with the timing and load capacitance given in I2C specification.

4.6.4 General IO AC characteristics

Output load supported for all other IO outputs such as GPIO outputs, PWM, UART is 50 pF max and 5 pF min.

UART interface supports maximum baud rate of 2 Mbaud when system clock frequency is 32 MHz.

All GPIO and PWM outputs will get reflected within 1 system clock period of 30ns on the output pins.

4.6.5 JTAG Interface AC characteristics

The JTAG interface is a 5-pin interface timed with respect to TCK input clock.

- TMS, TDI are inputs which are sampled by SoC on rising edge of TCK and is expected to be driven by JTAG host on falling edge of TCK.
- TDO is output from SoC driven on falling edge of TCK and expected to be sampled by JTAG host on rising edge of TCK.
- TRSTB is asynchronous signal.

Delays shown in the following table are with respect to SoC.

Output load supported for JTAG TDO output is 40 pF max and 5 pF min.

5 Register Access Methods

All SoC registers are accessed as Fixed Memory Mapped Registers.

The SoC does not contain any of these traditional x86 memory register types: Fixed IO, IO Referenced, Memory Referenced, PCI Configuration or Message Bus Registers.

5.1 Fixed Memory Mapped Register Access

Fixed Memory Mapped IO (MMIO) registers are accessed by specifying their 32-bit address in a memory transaction from the CPU core. This allows direct manipulation of the registers. Fixed MMIO registers are unmovable registers in memory space.

5.2 Register Field Access Types

Table 9. Register Access Types and Definitions

6 Mapping Address Spaces

The SoC supports a single flat Memory address space. The SoC does not support IO Address Space, PCI Configuration Space or Message Bus Space.

The Lakemont Processor core (LMT) can directly access memory space either through code fetches over ITCM or data fetches over DTCM or through memory reads and writes over AHB fabric.

This chapter describes how memory space is mapped to interfaces and peripherals in the SoC.

6.1 Physical Address Space Mappings

Processor supports 32b addressing. There are 4 GB (32-bits) of physical address space that can be used as:

- Memory Mapped I/O (MMIO I/O fabric)
- Physical Memory (System Flash/System SRAM)

The LMT can access the full physical address space. DMA Controller, the only other master agent on AHB fabric, can only access regions of physical address space allowed via the multi-layer SoC fabric - see more details under [SoC Fabric](#page-54-0) section.

All SoC peripherals map their registers and memory to physical address space. This chapter summarizes the possible mappings.

6.1.1 SoC Memory Map

The SoC Memory Map is divided up as follows:

- Processor Local APIC (LAPIC)
- I/O APIC
- SoC Configuration registers
- SoC Peripherals
- System Flash (Flash and ROM implemented as 2 distinct regions of OTP)
- System SRAM (Internal)

The LMT reset vector at 150h is located in OTP Code region of Intel® Quark™ microcontroller D2000. System addresses 0xFFFF_FFF0 and 0xFFFF_FFF8 are a special case by LMT and get aliased to reset vector.

Table 10 SoC Memory Map

Notes:

- LMT Reset Vector is located in OTP Code region at address 0x0000_0150
- All memory regions not covered in the SoC Memory Map are reserved. Reserved regions are unused. Reserved sections have been inserted to allow space for memory/peripheral address space to increase in derivative SoCs without re-arranging the address map. Access to Reserved regions trigger an interrupt to support debug of out of bound accesses. Writes to such regions have no effect while reads return a definite value depending on the interface.

AHB Fabric provides 4 HSELs to Flash Memory subsystem: Flash CREGs for configuration, Instruction Flash, OTP Code and OTP Flash Data.

Memory accesses are routed by the IO fabric based on fixed memory ranges that map to the SoC peripherals. These peripherals are: ADC, I2C, UART*, SPI*, GPIO, APB Timer, RTC and Watchdog Timer. The fixed regions assigned to each peripheral are listed in the table above. See the register maps of all peripheral devices for details.

LMT clock is gated by HW autonomously based on HALT detection. It is ungated by HW upon Interrupt assertion. There is an option to gate/ungate clock to Memory subsystem too with LMT clock. Other than LMT and Memory subsystem clocks, for all other functions, SW controls gate/ungate of their respective clocks.

6.2 SoC Fabric

The SoC Fabric is a multi-layer AHB fabric that provides interconnect between 2 Masters and 5 Slaves.

The two masters are LMT and DMA Controller – one on each AHB layer. The 5 slaves are: DMA Controller, Flash, SRAM, SCSS and APB peripherals. The multi-layer fabric allows multiple masters to access different slaves in parallel. When two or more masters try to access the same slave simultaneously, the slave arbitrates between the masters. With this topology, it is not possible for each master to access every slave connected to the SoC fabric. The LMT master can access all the 5 slaves. DMA Controller master can only access Flash Slave, SRAM Slave and APB Peripherals Slave.

Figure 5 Multi-Layer AHB fabric with ICM

From an address decode perspective, DMA controller can target all destinations inside Flash subsystem (Flash Configuration registers, Instruction Flash, 8KB OTP, 4KB OTP) and all destinations inside SRAM subsystem (SRAM and SRAM Configuration registers).

The Multi-layer AHB fabric also makes use of the HMASTER port on two ICM components ICM_SRAM and ICM_FLASH. The HMASTER port on these two ICMs is used by the slave for memory protection of the SRAM and Flash slaves. Each HMASTER port for each layer on the ICM has a different ID code, this allows the slave to identify which master is currently trying to access memory.

Table 11 Multi-Layer AHB Fabric Master ID List

APB Fabric has 10 slaves – GPIO, I2C Master/Slave, SPI Master, SPI Slave, 2 UARTs, ADC, RTC, WDT and Timers block. Even though DMA engine can perform concurrent transfers, single outstanding transaction limitation of AHB prevents simultaneous transfers to/from multiple peripherals.

7 Clocking

The Intel® Quark™ microcontroller D2000 clocking is controlled by the Clock Control Unit (CCU). There are 2 primary clocks in Intel® Quark™ microcontroller D2000, a System clock and an RTC clock. The sources and frequencies of the primary clocks are described in subsequent sections. The CCU uses the primary clocks to generate secondary clocks to sub modules in the SoC. The secondary clocks are gated and scaled versions of the primary clocks.

7.1 Signal Descriptions

[Table](#page-56-0) 12 provides the dependency on external signals/pins on clocking. Change from Atlas Peak is that there is no need to output system clock and RTC clock to platform.

Table 12. External Signals

7.2 Features

The CCU supports the following features:

- Supply of 32.768kHz RTC clock from internal crystal oscillator
- Supply of system clock from:
	- o an internal hybrid oscillator which can work in either 4/8/16/32 MHz Silicon RC oscillator mode (+/- 2% clock accuracy) or 20-32 MHz Crystal oscillator mode (+/- 100 ppm clock accuracy; depending on crystal connected)
	- o an external clock source (through HYB_XTALI input pin)
	- o 32.768kHz RTC clock (internal muxing)
- Perform clock gating on all output clocks
- Perform clock scaling on all output clocks

In "Low Power Compute" state of SoC, hybrid oscillator can be scaled down to 4 MHz with prescaler of 32 to get 125 kHz; or 32.768kHz (RTC clock wherein hybrid oscillator can be powered down).

In a minimalistic system configuration that does not require RTC clock or strict clock accuracy (< 100ppm) of system clock, such platforms can choose not to mount 32.768kHz XTAL and/or not to mount 32MHz XTAL and choose to work with 32MHz Silicon RC oscillator mode of hybrid oscillator. Intel® Quark™ microcontroller D2000 is designed to work with system clock only and does not mandate 32.768kHz RTC clock for power state transitions, if system/platform does not require RTC clock for its usecases.

7.2.1 System Clock - Hybrid Oscillator

When the system clock is sourced internally, a Cosmic Circuits hybrid oscillator [1] is used to generate the clock. The hybrid oscillator can be run in two modes, crystal or silicon mode depending on the frequency accuracy and current consumption requirements of the SoC. The hybrid oscillator contains the follow features:

- Crystal mode
	- o Generates 20-33 MHz clock
		- o +/-100ppm (dependent on crystal frequency tolerance)
		- o 2ms start-up time to reach +/-100ppm accuracy
- Silicon mode (default power up mode)
	- o Generates 4/8/16/32 MHz clock
		- o One time 10-bit factory trim
		- o +/-20,000ppm (after process trim)
		- o Temperature compensation block to limit frequency variation
 Ω 2us start-un time to reach +/-20.000ppm accuracy
		- 2us start-up time to reach $+/-20,000$ ppm accuracy
- 4mA $@$ 32MHz in crystal mode [silicon characterization at $~$ 650 uA $@$ 32 MHz]
- 450uA @ 32 MHz in silicon mode
- 300nA power down leakage current
- Operates with a supply range of 1.62-1.98V
- Outputs a rail-to-rail swing of 1.62-1.98V
- Power down mode to reduce power consumption within the SoC
- Glitch free mux for switching between hybrid and crystal oscillator clocks
- Bypass mode allows an external clock (fed through HYB_XTALI pin) to be provided through the hybrid oscillator. HYBOSC has to be configured in Crystal bypass mode (OSC0_EN_CRYSTAL=1, OSC0_EN_MODE_SEL=1, OSC0_BYP_XTAL=1)
- •

7.2.2 RTC Oscillator

A Silicon Gate Oscillator [2] is used to generate a 32.768kHz RTC clock. The RTC oscillator has the following features:

- Voltage operating range of 1.08-1.98V
- Accuracy of +/-20ppm
- Nominal current consumption of 150nA
- Power down mode consumption of 100nA [TBC]

- Bypass mode allows an external clock (fed through RTC_XTALI pin) to be provided through the RTC oscillator. To achieve this, OSC1_BYP_XTAL_UP=1 and OSC1_PD=0)
- 600mS start-up time to reach +/-20ppm

The Intel® Quark™ microcontroller D2000 is designed to operate without RTC clock as well, if platform does not require RTC clock. RTC clock is needed for any of the following reasons:

- Periodic waking in low power sleep state.
- Real Time Clock
- GPIO based wake (input debouncing/filter)

If above reasons are not required in a platform, then RTC oscillator can be disabled without connecting RTC XTAL on board. In this mode, only comparator based wake can be enabled to exit low power state.

7.2.3 Root Clock Frequency Scaling

The Intel® Quark™ microcontroller D2000 supports a single root clock with multiple supported root clock frequencies

- 1) 32MHz high accuracy Crystal Oscillator required for high accuracy applications.
- 2) 4/8/16/32MHz silicon Oscillator A lower power operating mode used by applications that do not require a high frequency accuracy.
- 3) 32.768 kHz entire SoC can operate out of 32.768 kHz clock as system clock (controlled by CCU_SYS_CLK_SEL register in SCSS) without enabling Hybrid Oscillator for such applications that require ultra low power without much compute performance.

7.2.4 Frequency Scaling

The Intel® Quark™ microcontroller D2000 supports a wide range of frequency scaling options to optimize power.

- 1) The root system clock frequency can be scaled to 4/8/16/32MHz
- 2) The Leaf peripheral clock can be independently scaled $@/2/4/8$ divisions

To apply a DFS setting the following procedure should be followed

- 1) Apply the clock divider value **CCU_XXX_CLK_DIV**
- 2) Apply the clock divider writing '0' **CCU_XXX_CLK_DIV_EN**
- 3) Apply the clock divider writing '1' **CCU_XXX_CLK_DIV_EN**

7.2.4.1 Peripheral DFS requirements

When using DFS it is the responsibility of firmware to adjust any settings in peripheral/timers to account for the frequency change. Example to achieve a UART baud rate of 115200 requires a different baud rate divider depending on the frequency.

7.2.4.2 Flash DFS requirements

When using DFS on the root fabric clock the flash wait states must be adjusted for both Flash instances. Refer to Memory Subsystem chapter for further details.

7.2.5 Dynamic Clock Gating

The Intel® Quark™ microcontroller D2000 supports a wide range of clock gating options

1) Each leaf clock can be dynamically gated by firmware

To apply a DCG the following procedure should be used.

- 1) Write '0' to the clock gate register **CCU_XXX_PCLK_EN**
- 2) The following hardware clock gating options are supported
	- a. UART low power autonomous hardware clock gating
	- b. SPI low power autonomous hardware clock gating

7.2.5.1 UART autonomous clock gating (ACG)

Both UART controllers support ACG mode (**CCU_UARTX_PCLK_EN_SW=0)**. ACG is asserted when the following occurs

- 1) Transmit and receive pipeline is clear (no data in the RBR/THR or TX/RX FIFO)
- 2) No activity has occurred on the SIN/SOUT lines
- 3) Modem input signals have not changed in more than one character time.

7.2.5.2 SPI autonomous clock gating (ACG)

All SPI controllers support ACG mode (**CCU_SPI_XX_PCLK_EN_SW=0).** ACG occurs when the SSIENR register has been written to 0.

8 Power Management

This chapter provides information on the power management and power architecture of the SoC.

Power architecture of SoC is based on the following premise:

- 1. There is no requirement to supply regulated voltage (1.8v or 3.3v) to platform components from SoC.
	- a. This dictates the max current specification of internal voltage regulator in the SoC.
- 2. Platform Components and SoC would operate from same battery source (eg coincell).
	- a. The IOs of SoC and the Analog components would be on the same rail as input battery source. Thus the electrical characteristics of SoC IOs (digital or analog) would be a function of battery rail and not regulated 1.8v/3.3v.
- 3. SoC has to generate a regulated 1.8v supply (DVDD) from battery input for operating its core logic.
	- a. There is level shifter in IOs between core voltage rail and IO rail (IOVDD). Similarly analog components such as ADC and Comparators take care of shifting from analog rail (AVDD) to core/digital rail or vice-versa.

SoC has 4 power input pins:

- 1. PVDD Used by internal voltage regulator only.
- 2. IOVDD Used by digital IO pads. Electrical characteristics of all external digital pins will be with respect to IOVDD.
- 3. AVDD Used by Analog components such as ADC and Comparators. Electrical characteristics of all external analog pins will be with respect to AVDD.
- 4. DVDD Used as SoC Core Voltage. Normal mode operating point is 1.8V. It can be fed either by internal voltage regulator's output (to be circled back in board); or from another regulated power supply from platform if internal voltage regulator is disabled. All of SoC internals will operate with DVDD.

PVDD, IOVDD, AVDD can be from the same power source with noise isolation, or can be independently supplied.

Power management of SoC is a function of how the individual component/device power state is managed. The various components in SoC that play a role in power management are Voltage Regulator, 32 MHz Oscillator, 32 kHz Oscillator, ADC, Analog Comparators, memories (SRAM, Flash), Processor Core, Peripheral controllers (digital logic) and IOs. Hence this chapter begins with a discussion on component power states and then moves on to create System power states based on component power states. The System power states are defined based on current draw requirement and latencies involved in entering or exiting a given power state. System power state is managed in Firmware/Software and not in hardware.

8.1 Component Power States

8.1.1 Voltage Regulator

Table 13. VR Power States

Note: Silicon OSC minimum current is ~200uA when configured for 4MHz operation (lowest power mode) – configuring the Voltage Regulator into Low Power is only be supported when clocking off either 32.768 kHz OSC or 4 MHz Silicon oscillator mode with prescaler set for 125 kHz or lower output.

"OFF" power state is entered only when internal regulator is disabled using VREN=L input pin and 1.8v rail (DVDD input) is fed directly from platform.

Voltage regulator in eSR mode has 90% efficiency down to 0.2 Imax (1 mA) and 70% efficiency down to 0.01 Imax (500 uA). In iLR mode, power consumption of VR is about 1% of delivered current.

The SoC power delivery is described in detail in the [Power Architecture](#page-71-0) section.

8.1.2 CPU

Table 14. CPU Power States

Processor in SoC does not support STOPCLK (for entering C2 state) but instead executing HALT instruction is used to enter C2 state wherein clock to processor core including LAPIC and IOAPIC is gated. The clock to LMT core can be gated after min 6 core clk cycles from xhalt detection (number of clock cycles is configurable and default set to 16 clock cycles). In Intel® Quark™ microcontroller D2000, processor is never power gated but only clock gated and hence processor state is always preserved. Clock is re-enabled to the processor if there is any wake event or any enabled interrupt.

Power Management

8.1.3 ADC

Table 15. ADC Power States

8.1.4 Comparator

Table 16. Comparator (CMP) Power States

8.1.5 32.768 kHz OSC

Table 17. 32.768 kHz OSC Power States

8.1.6 32 MHz OSC

Table 18. 32 MHz OSC Power States

8.1.7 SRAM

Table 19. SRAM Power States

There is no specific control to put the SRAM into above power states. The Intel® Quark™ microcontroller D2000 has a single always-on power domain (DVDD) and hence SRAM is always powered. SRAM state is always preserved. No special retention mode is required. STBY state is entered automatically by SRAM when the chip select to SRAM is inactive in a given clock cycle.

8.1.8 Peripherals

Table 20. Peripheral Power States

Power Management

8.2 System Power States

8.2.1 System Power State Diagram

Figure 6. System Power States

8.2.2 System Power State Definition

The Power Management states supported by the SoC are described in this section.

Table 21. SoC Power States

8.2.3 Power and Latency Requirements

The System power states are maintained and managed in FW.

Table 22. Power and Latency Requirements

- 1. LOW POWER COMPUTE has to work with Hybrid Oscillator set to Silicon oscillator mode with 4MHz output to limit 32MHz OSC at 180 uA.
- 2. "Any" state of comparator CMPH is dependent on current consumed versus number of external wakes to be enabled. Only needed number of comparators are in ON state. 6 High performance high power comparators are in OFF state.
- 3. It takes ~350 msec (typ) to power up the RTC XTAL oscillator. Power saving in switching off RTC XTAL oscillator is ~150 nA.
- 4. Low power wait or DEEP SLEEP RTC or DEEP SLEEP NORTC corresponds to VR in retention state (capable of sourcing only 300 uA max) and differ only in terms of which wake sources are enabled and can be decided by FW based on platform/system power usecases. If GPIO based wake is required, the retention voltage of VR has to 1.8V typical for digital IO pads to operate.
- 5. Exiting DEEP SLEEP NORTC state can be with Silicon oscillator set at 4 MHz (CCU_SYS_CLK_SEL set to Hybrid oscillator at entry) so that exit latency is < 2 usec. RTC oscillator will lock after 350 msec (typ).
- 6. In DEEP SLEEP NORTC, exit is possible only with comparator based wake. GPIO Wake, AON timer wake, RTC alarm wake are not available.
- 7. All entry/exit latencies are given assuming hybrid oscillator in Silicon mode and 4 MHz. Low power state Current numbers are given assuming 1 low power comparator enabled for wake.

8.2.4 Minimum Voltage Limits (Vmin)

Table 23. Minimum Voltage Limits

[Table](#page-70-0) **23** shows that DVDD has to be at 1.8V during normal operation. PVDD range is 2.0V to 3.63V limited by comparator. DVDD during retention has to be 1.8V if IOs are needed to be functional and can go below up to 1.2V (1.35V at RAR) if IOs are disabled/floating and provided Flash can work at that level (TBC – Check with TSMC). POR is only 1.8V DVDD during retention.

8.3 Power Architecture

The Intel® Quark™ microcontroller D2000 power architecture is given in [Figure](#page-71-0) 6 and uses a Retention Alternating Regulator (RAR). RAR works in two modes – normal mode wherein Switching Regulator is turned on sourcing 50 mA of max current and retention mode wherein linear regulator is turned on sourcing only 300 uA of max current.

The entire SoC core is under single power domain (1.8v regulated output rail from RAR) and is never power gated. Power saving is achieved by clock gating of logic and also putting the hard macros (such as ADC, comparators, oscillators, voltage regulator) in power down mode.

Tank capacitor at the output of LX is provided to ensure smooth switchover (no drop or droop) from Linear Regulator (retention mode) to Switching Regulator (normal mode) or vice-versa, provided current draw is restricted at less than 300 uA before transition. Follow the integration guidelines from Dolphin and also review the backend implementation with IP vendor.

Additionally in retention mode, RAR can supply only 300 uA of max current. Since the SoC is in single power domain fed by 1.8v regulated output from RAR, FW/SW has to ensure that enough components/devices are put into low power states such that overall current draw is less than 300 uA in LOW POWER WAIT / DEEP SLEEP states. No fail-safe scheme is implemented in the SoC.

VR_ROK_AVDB drives the POC rail of the I/O ring shutting down the I/O level shifters to prevent damage while the DVDD supply comes into regulation.

Implementation may choose to separate Analog GND (RAR, ADC, Comparators) and Digital GND (Std cells, Digital IO pads, memories, Oscillators) as separate pads and ground it to VSS plane in package. Similarly vrefp and agndref ports of ADC can be implemented as separate pads and bonded to AVDD and VSS respectively in package.

RST_N input uses low power comparator which has PVDD, AVDD and GND ports which are to be connected to PVDD, AVDD and VSS inputs respectively. REF1 port of RST_N comparator is connected to VREF_OUT from RAR.

Notes:

- 1. Current scheme assumes 40 ball QFN thus all digital and analog grounds are routed to the QFN ground pad.
- 2. Current scheme assumes 40 ball QFN thus several power rails are ganged together (e.g. ADC & Comparator).
- 3. ADC:
	- a. VREFP is double bonded to AVDD
	- b. AGNDREF is double boned to VSS
	- c. ADC Block has an internal LDO to create a clean 1.8V rail, DVDD_LDO is provided to allow bypassing of the LDO.

8.4 Power Management Unit (PMU)

8.4.1 Internal Voltage Regulator

Internal voltage regulator is enabled by pulling high VREN to PVDD.

- 1. PVDD/AVDD/IOVDD are applied together. All these rails are from same source.
- 2. After 240 usec of start-up time, Voltage regulator achieves regulated 1.8V DVDD in switching voltage regulator mode.
	- a. Till DVDD is stable, Power-on control (POC) of IO pads is kept asserted by an output (ROK_AVDB) from voltage regulator so that the level shifter inside IO pad between VDDPST and VDDcore is dis-engaged.
- 3. When DVDD is stable, Hybrid oscillator starts oscillating in Silicon RC oscillator mode outputting 4MHz +/- 40% (trimcode is not applied at this stage). HYBOSC takes 2 usec for lock time.
- 4. Internal voltage regulator provides a 0.95v +/- 15% internal reference voltage to the RST_N comparator within 2 msec. Till reference voltage is stable, voltage regulator sends an output to keep the RST_N comparator disabled (output $= 0$), thus keeping SoC under reset (internal power-on reset).
- 5. Once external RST_N input is deasserted and RST_N is internally enabled, SoC comes out of reset.
- 6. Processor is output of reset and fetches instruction at reset vector from flash. After some steps, firmware will apply the actual trimcode to HYBOSC at selected output frequency to get HYBOSC output to +/-2% accuracy.

Mint SoC Boot Waveform for Internal VR mode

8.4.2 External Voltage Regulator

Internal voltage regulator is disabled by grounding VREN to GND. In this case, DVDD voltage input is supplied by an external voltage regulator. Here DVDD has to be applied before IOVDD.

- 1. PVDD/AVDD/DVDD are applied together.
- 2. Wait for DVDD rail to ramp-up to stable regulated value.
- 3. As DVDD is stable, Hybrid oscillator starts oscillating in Silicon RC oscillator mode outputting 4MHz +/- 40% (trimcode is not applied at this stage). HYBOSC takes 2 usec for lock time.
- 4. After 50 usec minimum time, apply IOVDD rail. This is done to ensure that there is no crowbar current between VDDPST (IOVDD) and VDDcore (DVDD) in the level shifter inside digital IO Pads.
- 5. Internal voltage regulator provides a 0.95v +/- 15% internal reference voltage to the RST_N comparator within 2 msec. Till reference voltage is stable, voltage regulator sends an output to keep the RST_N comparator disabled (output $= 0$), thus keeping SoC under reset (internal power-on reset).
- 6. Once external RST_N input is deasserted and RST_N is internally enabled, SoC comes out of reset.
- 7. Processor is output of reset and fetches instruction at reset vector from flash. After some steps, firmware will apply the actual trimcode to HYBOSC at selected output frequency to get HYBOSC output to +/-2% accuracy.

9 Power Up and Reset Sequence

This chapter provides information on the following topics:

- Power Up Sequences
- Power Down Sequences
- Reset Behavior

9.1 Power Up Sequences

There are two cases of power up:

- a. RST_N triggered Power Up (Any state to ACTIVE state). Covers Power recycling.
- b. From any Low Power State to ACTIVE state (based on any of configured wake events)

Hardware (PMU) supports enabling on-die RAR Voltage Regulator. Hybrid Oscillator and RTC Oscillator during the power up sequence. Rest of the SOC components are to be enabled back by FW.

9.1.1 RST_N Triggered Transition to ACTIVE state

When RST_N is asserted following PVDD power cycle or otherwise, the following power up sequence occurs:

- 1. RST_N is asserted by platform. This covers the case of Power recycle as well. RST N is kept asserted till PVDD input rail is within the operating range [2.0v-3.6v]. SoC asserts POR_RST#, COLD_RST#, WARM_RST#. RST_N is to be kept asserted for tROK_PROG (~250 usec; TBC) irrespective of whether internal voltage regulator is enabled or disabled.
	- a. On-die RAR voltage regulator (VR) executes its powers up sequence whenever PVDD recycles. At other times of RST_N assertion, RAR Voltage regulator is not affected. If power cycled, RAR starts to regulate in eSR Switching Regulator mode with 1.8V voltage output.
	- b. Hardware enables Hybrid Oscillator and RTC Oscillator. This is based on the default values of OSC0_CFG0/1 and OSC1_CFG registers. Hybrid oscillator is enabled in 4 MHz Silicon Oscillator mode with default TRIM code of 0. At this stage, there is no expectation to have 2% accurate oscillator output but just to have clock cycles for starting operation. Actual trimcode based on trimming is applied by FW later based on trimcode stored in Flash. Oscillators will start of oscillate once DVDD is stable above 1.62V.
- 2. RST_N is deasserted by platform. RST_N is expected to be asserted for tROK_PROG (250 usec; TBC) to account for internal regulator startup time. POR_RST# is removed.
- 3. RAR Voltage Regulator is set to eSR Switching Regulator mode with 1.8V Voltage select. This is ensured by the default values of AON_VR register.

- 4. PMU generates a strobe on VSEL_STROBE to RAR to put it in eSR mode at 1.8V VSEL_IN. Pulse width of VSEL_STROBE is based on PM_WAIT.VSTRB_WAIT register. At the positive edge of VSEL_STROBE, RAR deasserts ROK_BUF_VREG (if it is enabled/selected by VR_EN input).
	- a. When RAR is power recycled, RAR will default to eSR 1.8V mode automatically. However at other times of RST_N, RAR may be in other mode (for example, qLR Linear Regulator and non 1.8V). Hence this strobing is done by PMU to get it predictably back to eSR 1.8V regulation mode.
- 5. PMU waits for ROK_BUF_VREG from RAR to be asserted so that voltage regulator (VR) has attained regulation. In case RAR VR is bypassed by VR_EN input pin, RAR VR keeps ROK_BUF_VREG asserted always.
- 6. COLD_RST# and WARM_RST# are released. Clocks to LMT Processor, Memory Subsystem (SRAM and Flash) are active.
- 7. Host processor LMT starts to execute from reset vector. Later on, Firmware can enable the needed components such as ADC, comparators, peripheral subsystem to put the SoC into ACTIVE/Normal mode of operation.

9.1.2 Low Power State to Active

For those low power states not requiring voltage regulator to be put into retention (linear regulator) mode, below sequences are not required and can be handled by SW/FW by powering up needed components based on System Power State. Below sequence is applicable when voltage regulator was earlier put into retention/linear regulator mode with core output voltage set to either 1.8V or lower (say 1.35V).

When the SoC is in any of Sleep states and a wake event is triggered, the following sequence occurs:

- 1. An enabled wake event is triggered and latched within the SoC
- 2. The RTC Power Down input is asynchronously de-asserted by PMU in order to restart the 32 kHz clock
	- a. Powering down the RTC oscillator is an optional step when entering sleep (say DEEPSLEEP_NORTC state).
- 3. Hybrid Oscillator Power Down input is asynchronously deasserted by PMU. Hybrid oscillator will come up in the same settings as it were at the time of entering low power state.
- 4. Based on CCU_SYS_CLK_CTL.CCU_SYS_CLK_SEL programmed by FW at the time of entering into low power state, sys_clk will take either Hybrid oscillator output or RTC clock output. This step exits based on the LOCK time of selected oscillator. If CCU_LP_CLK_CTL.CCU_EXIT_TO_HYBOSC was set to 1'b1, then PMU ensures that sys_clk takes hybrid oscillator output.
- 5. Once the sys_clk starts ticking, Host Processor will get the wake interrupt. LMT starts to execute.
- 6. FW to restore clock settings for normal mode: OSC0_PD=0, OSC1_PD=0 or 1 (1'b1 if RTCOSC is not needed in active state), CCU_SYS_CLK_SEL = 1 (HYBOSC) to be updated to proper values.
- 7. FW to program HYB_OSC_PD_LATCH_EN = 1, RTC_OSC_PD_LATCH_EN=1 so that OSC0_PD and OSC1_PD values directly control the oscillators in active state.
- 8. FW to make WAKE_MASK[31:0] to all-ones (all wake disabled) so that any future interrupt in active power state does not interfere with wake related logic (such as powering down oscillators etc).

- 9. FW has to bring back RAR voltage regulator to eSR normal mode before it enables other SoC components for normal mode of operation.
	- a. Set AON_VR.VREG_SEL to eSR/normal mode.
	- b. Wait for 2 usec (TBC) for RAR to switch back to eSR normal mode delivering up to 50 mA max current.
	- c. Clear AON_VR.ROK_BUF_VREG_MASK.
- 10. If (SCSS AON_VR.VSEL == 1.35V) { // exiting from 1.35V core voltage mode
	- a. FW to set SCSS.AON_VR.VSEL = $0x10$; // Set to 1.8V. This will take effect only for VSEL_STROBE. Perform read modify write along with passcode.
	- b. FW to do Voltage strobing in next access to AON_VR register after setting up VSEL previously. SCSS.AON_VR.VSEL_STROBE = 1; // Bit 5. Perform read mod write along with passcode
	- c. Wait for 1 usec;
	- d. FW to reset SCSS.AON_VR.VSEL_STROBE = 0 ; // Bit 5. Perform read mod write along with passcode
	- e. Wait for 2 usec; // Wait for 1.8V to take effect
	- f. FW to reset SCSS.AON_VR.ROK_BUF_VREG_MASK = 0; // Perform read modify write along with passcode.
	- g. Wait for 1 usec; // 1 usec for DVDD to be stable at 1.8V before changing HYBOSC and Flash low voltage mode.
	- h. FW to move HYBOSC from low voltage retention mode to normal 1.8V mode. SCSS.OSC0_CFG0.OSC0_HYB_SET_REG1.OSC0_CFG0[0] = 0; i. FW to Put Flash from LVE mode to Normal Voltage mode
	- $FlashCtrl.CTRL.LVE_MODE = 0;$
- 11. Switch back hybrid oscillator to 32MHz frequency.
	- a. FW to set CCU_SYS_CLK_CTL.CCU_SYS_CLK_DIV to needed divisor value.
	- b. FW configures Hybrid Oscillator (OSC0_CFG0/1 registers) to 32 MHz Silicon oscillator mode while applying trimcode specific to 32 MHz frequency.
- 12. Firmware can enable the needed components such as ADC, comparators, peripheral subsystem to put the SoC into ACTIVE/Normal mode of operation including enabling PERIPH_CLK_EN to 1'b1.
	- a. Note that none of the resets (say WARM_RST#) is asserted during power state transitions.
	- b. since host processor subsystem is never powered down in low power state, state of the CPU core as well as other SoC components are preserved. Hence FW/OS is not expected to do a save/restore operation, thus saving time in exit latency.

9.2 Power Down Sequences

Power down sequence is totally executed by FW depending on the low power state to enter. PMU does not play any part in this sequence. Before entering low power state, the intended wake sources have to be enabled.

The possible wake sources/events that can be configured by FW/SW while entering a low power state is as below. Corresponding WAKE_MASK[31:0] and/or CCU_LP_CLK_CTL.WAKE_PROBE_MODE_MASK register bits specific to the wake source of interest has to be unmasked (set to 0) while remaining bits are to be masked (set to 1) to prevent unwanted wake.

One or more possible wake sources can be simultaneously enabled in a given low power state. RST_N assertion will automatically transition the SoC to normal/active state (4 MHz Si OSC mode) as given in section 9.1.1.

CLTAP Probe mode request is generated by setting CLTAP_CPU_VPREQ.assert_vpreq to 1 (TAP instruction 0x70 Bit0) through JTAG interface. In deep sleep state, ensure TCK frequency is less than 32 kHz (system clock frequency at that state divided by 4).

For setting GPIO level triggered interrupt as wake source, GPIO controller has to be programmed as below for a specific GPIO pin x of interest:

- GPIO_INTEN $[x] = 1$. Enable interrupt for that particular GPIO pin.
- GPIO_INTYPE_LEVEL[x] = 0; Level sensitive interrupt.
- GPIO INT POLARITY[x] = 1; Active-high level interrupt (0 to 1 on GPIO pin will wake; default state of this GPIO input pin shall be 0). Set this register bit to 0 if it has to be active-low level interrupt. 0 level to trigger interrupt.
- GPIO_DEBOUNCE $[x] = 0$. No debounce as there is no clock running.

 $GPIO_LS_SYNC[x] = 0$. Not synchronized as there is no clock running to synchronize. (d) and (e) are important settings.

9.2.1 Active to Any Low Power State

For those low power states not requiring voltage regulator to be put into retention mode, the following sequences are not required and can be handled by SW/FW by powering down or enabling clock gating of specific components not in use based on System Power State. For example, Low Power Halt state is mainly halting processor and optionally memory system by executing HALT instruction while peripherals can be in operation.

Whenever user application / software wants to enter any of low power state (having voltage regulator in retention mode) from ACTIVE state, the following sequence occurs: All steps are executed by Firmware.

- 1. SW/FW to ensure all interrupts are serviced and no interrupt pending.
- 2. SW/FW to ensure that all high power components such as ADC, highperformance comparators ([5:0]), unneeded low power comparators (18:6]), are powered down and peripheral subsystem clock gated (PERIPH_CLK_EN = 0).

- 3. SW/FW must enable the needed interrupt sources for wake and mask all other interrupt sources. Wake sources can be any of enabled low power comparators, any GPIO based interrupt wake, AON Periodic Timer expiry, RTC alarm interrupt. Additionally system automatically wakes up to RST_N assertion.
	- a. Program WAKE_MASK.WAKE_MASK[31:0], CCU_LP_CLK_CTL.WAKE_PROBE_MODE_MASK registers identical to Interrupt Mask registers.
- 4. Program HYB_OSC_PD_LATCH_EN = 0, RTC_OSC_PD_LATCH_EN=0. This ensures that powering down of oscillators is delayed by hardware till core executes HALT at last step in this sequence.
- 5. Program CCU_LP_CLK_CTL.CCU_EXIT_TO_HYBOSC to 1'b1. This ensures that at exit, hardware will switch system clock to Hybrid oscillator clock so as to minimize exit latency by running at higher frequency than RTC clock.
- 6. If RTC clock is not needed during low power state (no AON Timer, RTC, GPIO interrupt), FW to program OSC1_CFG0.OSC1_PD to 1'b1. RTC Oscillator will actually get powered down only at last step when core enters HALT.
- 7. FW to program OSC0_CFG1.OSC0_PD = 1. Hybrid Oscillator will actually get powered down only at last step when core enters HALT.
- 8. FW configures Hybrid Oscillator (OSC0_CFG0/1 registers) to 4 MHz Silicon oscillator mode while applying trimcode specific to 4MHz frequency. Note that Hybrid oscillator shall not be disabled to effect this change if CCU_SYS_CLK_SEL is set to hybrid oscillator as it stops the clock to processor. This step ensures that current consumed by hybrid oscillator is reduced to ~180 uA levels as max retention mode current supply from RAR is 300 uA.
- 9. FW sets CCU_SYS_CLK_CTL.CCU_SYS_CLK_DIV to div-by-32 (or lower; TBC) to reduce system clock frequency to 125 kHz (or lower; TBC). This step is needed to reduce dynamic power of processor and digital logic so that overall current draw by SoC is now less than 300 uA.
- 10. If (retention voltage in low power state $=$ = 1.35V) { // change to 1.35V in eSR mode. This step is not needed if retention voltage is unchanged at 1.8V itself.
	- a. FW to move HYBOSC to low voltage retention mode. SCSS.OSC0_CFG0.OSC0_HYB_SET_REG1.OSC0_CFG0[0] = 1;
	- b. FW to Put Flash to LVE mode from Normal Voltage mode FlashCtrl.CTRL.LVE_MODE = 1;
	- c. FW to set SCSS.AON_VR.VSEL = $0xB$; // Set to 1.35V. This will take effect only with VSEL STROBE. Perform read modify write along with passcode.
	- d. FW to set SCSS.AON_VR.ROK_BUF_VREG_MASK = 1; // Perform read modify write along with passcode.
	- e. FW to do Voltage strobing in next access to AON_VR register after setting up VSEL previously. SCSS.AON_VR.VSEL_STROBE = 1; // Bit 5. Perform read mod write along with passcode
	- f. Wait for 1 usec;
	- g. FW to reset SCSS.AON_VR.VSEL_STROBE = 0 ; // Bit 5. Perform read mod write along with passcode
	- h. Wait for 2 usec; // Wait for 1.35V to take effect

- 11. FW to configure RAR Voltage regulator to operate in retention mode (Linear Regulator). This step is needed as RAR in eSR switching regulator mode is very inefficient (consumes more power) at low current loads.
	- a. Set ROK_BUF_VREG_MASK as AON_VR.ROK_BUF_VREG would go low during retention mode. This ensures that logic that uses ROK_BUF_VREG output from RAR are not falsely triggered.
	- b. Set AON_VR.VREG_SEL to qLR/retention mode. VSEL_IN is set to 1.8V. VSEL_STROBE strobing is not required here as voltage is not changed. Don't do any voltage programming of RAR as Retention voltage less than 1.8V is not POR, as it would make all IO pads nonfunctional. After 20 usec (no need to wait for this time), RAR would come up in qLR retention mode delivering 300 uA max current. External tank capacitor ensures that DVDD supply is maintained without any drops or droops during this transition.
- 12. If wake source is any of AON Timer, RTC, GPIO interrupt, program CCU_SYS_CLK_CTL.CCU_SYS_CLK_SEL to RTC Oscillator. This step is not needed if wake source is only comparator and/or GPIO level triggered interrupt (without GPIO debouncing).
- 13. SW/FW to execute HALT instruction.
	- a. Once core is halted, PMU will automatically clock gate processor clock and memory subsystem clock. This reduces dynamic power consumed by processor and memory subsystems (provided CCU_LP_CLK_CTL. CPU_CPU_HALT_EN and CCU_LP_CLK_CTL.CPU_MEM_HALT_EN are enabled). And also PMU will power down Hybrid oscillator and RTC Oscillator as per respective OSC0_PD and OSC1_PD register bits.

9.2.2 Power Sequence Analog Characteristics

The following table describes the analog characteristics of the blocks used in the SoC power sequences.

Table 24. Power Sequence Analog Characteristics

9.2.3 Handling Power Failures

Power failure can occur if main power or battery is removed or brownout occurs.

On-die voltage regulator requires minimum 2.0V at PVDD to ensure 1.8V DVDD for normal operation.

The SoC does not provide any brownout detection or indicator and relies on external platform agents to handle brownout and to assert RST_N input pin.

9.3 Reset Behavior

The SoC supports three types of reset:

- Power On Reset
- Cold Reset
- Warm Reset

9.3.1 Power On Reset

The SoC provides an on-die circuitry to provide a power on reset when main power is applied. The power on reset is asserted when the SoC is powering up and is released when VCC_AON_1P8 has crossed a given threshold for a certain length of time.

The only mechanism to trigger a power on reset is to remove and then re-apply main power.

Only indication to SoC that power recycling happened is RST_N input pin. Whenever there is power recycle, RST_N is expected to be asserted and then de-asserted once input power rail PVDD is within the operating voltage range [2.0V to 3.6V]. In case of a power recycle, RST_N has to be kept asserted till DVDD core voltage is also stable (internal voltage regulator has attained regulation, tROK_PROG < 100 usec). Hence RST_N is taken as proxy of power-on reset

RST_N could be asserted at other times as well to trigger a complete SoC reset. Only PVDD power recycle will restart the on-die voltage regulator. RST_N will reset the entire SoC including System Control Subsystem (SCSS) and registers.

When RST N is triggered, the following sequence occurs:

- 1. A RST_N event is detected.
- 2. SCSS asserts POR_RST#, COLD_RST# and WARM_RST#.
- 3. Waits till RST_N is deasserted. Then deasserts POR_RST# used by SCSS logic (PMU, CCU).
- 4. RAR Voltage Regulator is set to eSR Switching Regulator mode. Ensured by default value of configuration register (AON_VR.VREG_SEL).
- 5. The RTC Power Down input is de-asserted. Hybrid Oscillator is enabled in Silicon Oscillator mode at 4MHz Frequency Select. This is done by default values of corresponding SCSS registers (OSC0_CFG0/1, OSC1_CFG0) which are reset at cold reset.
	- a. This is to ensure that if the cold reset was triggered while in a Sleeping state with the RTC disabled, the 32 kHz clock and Hybrid Si Oscillator 4MHz get restarted.
	- b. The mux select config register (CCU_SYS_CLK_SEL) to choose system clock is automatically set to select Hybrid Si Oscillator [Intel® Quark™ microcontroller D2000 can work without RTC clock].
	- c. Once the clock is running, the PMU accepts the cold reset request and asserts both COLD_RST# and WARM_RST#.
- 6. PMU generates a strobe on VSEL_STROBE to RAR to put it in eSR mode at 1.8V VSEL_IN. Pulse width of VSEL_STROBE is based on PM_WAIT.VSTRB_WAIT register. At the positive edge of VSEL_STROBE, RAR deasserts ROK_BUF_VREG (if it is enabled/selected by VR_EN input).
	- a. When RAR is power recycled, RAR will default to eSR 1.8V mode automatically. However at other times of RST_N, RAR may be in other mode (for example, qLR Linear Regulator and non 1.8V). Hence this strobing is done by PMU to get it predictably back to eSR 1.8V regulation mode.
- 7. PMU waits for ROK_BUF_VREG from RAR to be asserted so that voltage regulator (VR) has attained regulation. In case RAR VR is bypassed by VR_EN input pin, RAR VR keeps ROK_BUF_VREG asserted always.
- 8. COLD_RST# and WARM_RST# are released.

9.3.2 Cold Reset

A cold reset will trigger a power cycle of the Host domain (Processor Subsystem, Memory Subsystem, Peripheral Subsystem and Fabric) and trigger a reset of registers both in the Host and AON (SCSS) domains. There is no reset cycling of most of AON domain (SCSS) logic and also certain SCSS registers due to a cold reset.

Table 25. Cold Reset Triggers

When a cold reset is triggered, the following sequence occurs:

- 1. A cold reset event is detected.
- 2. SCSS asserts COLD_RST# and WARM_RST#. Note that POR_RST# is not asserted; RAR Voltage Regulator is not affected and continues to operate in same mode as before.
- 3. Wait for cold reset triggers to get cleared.
	- a. Note that RSTC.COLD register bit gets cleared at COLD_RST#.
- 4. COLD_RST# and WARM_RST# are released.

9.3.3 Warm Reset

A warm reset will trigger a reset of all Host domain logic and all non-sticky registers. There is no power cycling of the Host or AON domains due to a warm reset. Intel $^{\circledast}$ Quark™ microcontroller D2000 is single always-on power domain for the entire design (DVDD).

Table 26. Warm Reset Triggers

When a warm reset is triggered, the following sequence occurs:

- 1. A warm reset event is detected.
- 2. SCSS asserts WARM_RST#. This resets host domain including processor core.
- 3. Wait for Warm Reset triggers to get cleared.

- a. Note that RSTC. WARM register bit gets cleared at WARM_RST#. Similarly watchdog timer, processor and other interrupt generation blocks are reset by warm reset.
- 4. WARM_RST# is released.

Note 1: Following interrupt sources are not to be redirected to trigger warm reset as they will not get cleared due to warm reset, leading to SoC permanently under warm reset. Only a power recycle or RST_N recycle will recover this condition.

- 1. RTC Interrupt (INT_RTC_HOST_HALT_MASK register shall remain masked permanently – default value)
- 2. Comparator Interrupt (INT_COMPARATORS_HOST_HALT_MASK[18:0] register shall remain masked permanently – default value)
- 3. AON Timer Interrupt (INT_AON_TIMER_HOST_HALT_MASK register shall remain masked permanently – default value)

10 Thermal Management

10.1 Overview

The Intel® Quark™ microcontroller D2000 SoC does not contain an integrated thermal sensor.

Ambient temperature = -40° c to $+85^{\circ}$ c.

11 Processor Core

The SoC provides a single core x86 processor with separate and independent Tightly Coupled Memory (TCM) Interfaces for Instruction and Data.

11.1 Features

- Single Processor Core
- Single Instruction 5-stage pipeline
- 32-bit Processor with 32-bit Data Bus
- Native 32b AHB-Lite Interface
- 64b Data TCM Interface to Internal System SRAM
	- o Data Transfers for addresses matching the Internal System SRAM range will appear on the Data TCM Interface and transfers to address outside this range will appear on the AHB-Lite Interface
- 64b Instruction TCM Interface to Internal System Non-Volatile-Memory (NVM)
	- o Instruction Fetches for addresses matching the Internal NVM range will appear on the Instruction TCM Interface and transfers to address outside this range will appear on the AHB-Lite Interface
- Support for IA 32-bit with Pentium x86 ISA compatibility
	- o Reset Vector of 0x0000_0150
	- o Little Endian
- Support for CPUID Instruction
- Support for long NOP Instruction
- Time Stamp Counter (TSC) accessed with the RDTSC instruction

- Support for Paging included although not required for the Intel® Quark™ microcontroller D2000 use case
	- o 2 Entry Instruction TLB (Translation Look-aside Buffer)

	o 2 Entry Data TLB (Translation Look-aside Buffer)
	- 2 Entry Data TLB (Translation Look-aside Buffer)
	- Single cycle $32bx32b \rightarrow 32b$ Multiplier (IMUL Instruction)
- Integrated Intel® Quark™ microcontroller D2000 Interrupt Controller (MVIC) with support for 32 IRQs - some may be unused in Intel® Quark™ microcontroller D2000.
- Supports C0 and C1 Processor Power States
	- o Supports Interrupt as Wake Event from C1

	o Both Time Stamp Counter and LVT Timer ru
	- o Both Time Stamp Counter and LVT Timer run in C1 State
	- STOP CLOCK feature is not supported and the xstpreqnn toplevel input is tied off.
	- o Intel® Quark™ microcontroller D2000 implements C2 capability of processor by clock gating processor upon detecting HALT instruction
	- o Time Stamp Counter and LVT Timer do not run when Intel® Quark™ microcontroller D2000 clock gates processor

Note: The processor does not provide an x87 Floating Point Unit (FPU) and does not support x87 FPU instructions.

11.2 Processor Memory Map

The processor memory map for the Intel® Quark™ microcontroller D2000 SoC shall cater for the planned subsequent derivative SoCs which are likely to include variations in the amount of NVM and SRAM included in the SoC. [Figure](#page-89-0) 8 shows the generic processor memory map that will be applicable to Intel® Quark™ microcontroller D2000 and its derivatives.

Figure 9. Generic Intel® Quark™ microcontroller D2000 Processor Memory Map

The CPU address map for Intel® Quark™ microcontroller D2000 is as follows:

Notes:

- Reset Vector from CPU is mapped to 0x150 and falls into OTP Code region.
- OPEN: In which of the above regions will LMT implement "wrap-around-protect"?
- This is Lakemont Memory view not Intel® Quark™ microcontroller D2000 Memory view.
- N1: LMT routes memory writes to Instruction* regions towards AHB. These writes are dropped by SoC's Memory subsystem.
- N2: LMT routes writes to Data ROM region towards AHB. These writes are dropped by SoC's Memory subsystem.
- N3: These requests are treated, by SoC, in the same manner (including Access Control) as normal memory read requests from LMT.
- N4: LMT routes such requests towards AHB. These requests are treated, by SoC, in the same manner (including Access Control) as normal memory read requests from LMT.
- Note that OTP Data (Data ROM Memory Type in 1st column of above table) resides on AHB interface – from Lakemont perspective.
- Code accesses, if any, to DATA SRAM or DATA ROM regions (in 1st column of above table) are routed to AHB by LMT. Similarly, data accesses, if any, to Instruction Flash or Instruction RAM or Instruction ROM (in 1st column of above table) are routed to AHB by LMT.
- Self-modifying code is not supported in Intel® Quark™ microcontroller D2000.
	- o However, if it happens, LMT will route writes to Instruction Flash region towards AHB. These writes are dropped by SoC's Memory subsystem. A following read from LMT will appear on ITCM returning incorrect/previous value in Flash.
- Intel® Quark™ microcontroller D2000 always completes a request on ITCM, DTCM and AHB interfaces when address is out of bounds or there is an access violation.
- System addresses 0xFFFF_FFF0 and 0xFFFF_FFF8 are a special case by LMT and get aliased to reset vector.

11.3 Main Fabric Bus Cycle Processing

The Lakemont CPU supports the following AHB-lite cycles:

- Code Read
- Memory Read (Data)
- Memory Write (Data)

The following sections describe the behavior of the SoC for all these supported types.

11.3.1.1 Code Reads

Code Reads that fall within the I-TCM memory address range will be forwarded to the I-TCM interface. Code Reads outside of the ITCM range will be forwarded by default to the AHB-lite fabric, this includes code reads to the DTCM range. Immediate data in code fetches are also routed to AHB.

Access latency, as seen by the processor, to both Flash Code and OTP Code regions is the same.

Address on ITCM interface is 19b DW address. Hence, total ITCM address space is 2MB of space. Lowest address bit is always driven to 0 by the processor since ITCM is 64b wide.

Address, issued by LMT, on ITCM is relative address. It starts from offset 0 with respect to base address of 0x0.

All accesses on ITCM are 8B address aligned and 64b access. There is no burst and no byte-enables. Hence, processor performs 2 read accesses for every 16B cacheline.

Processor cannot write to ITCM interface (either as probe mode or in any other way).

Protocol on ITCM allows for variable wait-state from Flash.

Processor routes all probe mode accesses towards AHB-Lite.

Attribute HPROT[0] = 0 on AHB-Lite interface indicates Code reads while $HPROT[0] =$ 1 indicates Data accesses.

There is no burst support on AHB interface.

11.3.1.2 Memory Reads and Memory Writes

Memory accesses (data), both read and writes that fall within the D-TCM memory range will be forwarded to the D-TCM interface. Memory accesses outside of the D-TCM range will be forward to the AHB-lite fabric.

Memory accesses (data) are not allowed to access the I-TCM. Accesses to that region will be forward to the AHB-lite fabric.

Processor only issues a single 32b request. All accesses on DTCM are 8B address aligned and 64b access. Byte Enables indicate which 32b on 64b DTCM is valid – for both reads and writes.

Address on DTCM interface is 18b DW address. Hence, total DTCM address space is 1MB. Lowest 3 address bits are always driven to 0's by the processor.

Address, issued by LMT, on DTCM, is relative address and starts from offset 0 with respect to base address of 0x0028_0000. Only 512KB [0x0028_0000 to 0x002F_FFFF] is mapped to DTCM on LMT.

LMT is an in-order machine with a single instruction in flight. AHB response in the fabric for a memory write makes the write on AHB-Lite interface posted. Since there is no L1 cache for processor, all transactions are uncached and hence serialized by processor.

Processor routes all probe mode accesses towards AHB-Lite.

11.3.1.3 IO Reads and IO Writes

IO reads and writes are under SW control and SW must not issue them. These requests are aliased into Memory address space on AHB-Lite interface.

11.3.1.4 Interrupt Acknowledge

Interrupt Acknowledge cycles are expected to be completed by the integrated MVIC. There is no external interrupt controller connected to the AHB fabric that could provide the interrupt vector information.

11.3.1.5 Special Cycles

The Lakemont processor provides special bus cycles to indicate that certain instructions have been executed or certain conditions have occurred internally. This section describes how the Intel® Quark™ microcontroller D2000 SoC handles each of the special cycles.

11.3.1.5.1 Write-Back/Sync Special Cycle

The Writeback Special Cycle is generated by an x86 processor when a WBINVD instruction is executed.

As the processor does not have an L1 cache, the WBINVD instruction is not required to be executed and the Writeback Special cycle is not expected to appear on the main fabric bus interface.

If the code contains a WBINVD, the processor's behavior shall be to be to treat it as a NOP.

11.3.1.5.2 Flush Ack Special Cycles

First Flush Acknowledge and Second Flush Acknowledge Special Cycles are generated by Lakemont-class processor to indicate the completion of a cache flush in response to the FLUSH# pin being asserted.

As the processor does not have a L1 cache, the FLUSH# pin will not used and Flush Acknowledge Special Cycles are not expected to appear on the AHB-Lite interface.

If the processor generates a Flush Acknowledge Special cycle, it will be internally acknowledged to allow the processor to make forward progress but it will not appear on the AHB fabric or on any other external interface

11.3.1.5.3 Flush Special Cycle

The Flush Special Cycle is generated by an x86 processor when an INVD instruction is executed.

As the processor does not have an L1 cache, the INVD instruction is not required to be executed and the Flush Special cycle is not expected to appear on the main fabric bus.

If the code contains an INVD, the processor's behavior shall be to be to treat this instruction as a NOP.

11.3.1.5.4 Shutdown Special Cycle

The Shutdown Special Cycle is generated by Lakemont when a triple fault occurs. The special cycle indicates that the processor has ceased program execution and is in the shutdown state. The processor must be reset in order to exit the shutdown state.

If the processor generates a Special Cycle, it will be internally acknowledged and an output on the external interface will be asserted. This signal can be used by an external system agent to issue a reset to the processor.

In response to Shutdown, Intel® Quark™ microcontroller D2000 performs a warm reset of SoC and cause of reset is logged in a sticky register.

11.3.1.5.5 Halt Special Cycle

The Halt Special Cycle is generated by an x86 processor when a HLT instruction is executed.

If the processor generates a Halt Cycle, it will be internally acknowledged and an output on the external interface will be asserted. This signal can be used by an external system agent to issue take an action for power management or to track the state of the processor.

When Intel[®] Quark[™] microcontroller D2000 detects Halt cycle, it waits for a programmable number of clocks (>6 clocks) before clock-gating the processor. Any break event (interrupt or Probe Mode activity via xrsnn interface) restarts the clock. Clock is not gated if any break event is pending. LMT JTAG activity does not ungate clock.

11.3.1.5.6 Stop Grant Acknowledge Special Cycle

The Stop Grant Acknowledge Special Cycle is generated by an x86 processor when the processor enter the Stop Grant state in response to STPCLK# being asserted.

If the processor generates a Stop Grant Acknowledge Special Cycle, it will be internally acknowledged and an output on the external interface will be asserted. This signal can be used by an external system agent to issue take an action for power management or to track the state of the processor.

Intel® Quark™ microcontroller D2000 does not assert STPCLK# and hence Stop Grant Acknowledge cycle is not generated by processor.

11.3.1.6 MSI

The SoC AHB fabric will not send MSIs to the processor so an external interface for MSIs is not required.

MSIs may be exchanged between the components within integrated MVIC. However, these MSIs remain internal to the processor sub-system and not no appear on the AHB fabric.

BLV SoC does not assert NMI pin of LMT.

11.3.1.7 End of Interrupt

The processor subsystem provides an integrated MVIC. There are no other interrupt controllers in the SoC. As a result, there is no need to signal EOI information to any agent connected on the AHB fabric.

EOI information may be exchanged between the components within MVIC.

11.3.2 Mapping FSB to AHB

The processor core is a master on the internal SoC AHB fabric and a gasket to convert from FSB protocol to AHB is provided. The operation of the gasket and the interface to the AHB fabric is transparent to software.

11.3.2.1 Byte Enables

For read accesses on AHB-Lite interface, Lakemont always asserts all byte enables.

Lakemont does not issue burst reads or writes on AHB-Lite interface. For single writes, byte enable handling is described in the following paragraphs.

Lakemont allows all combination of byte enables for 32-bit accesses provided that there is at least one enabled byte and that the enabled bytes are contiguous. This gives 10 valid 4-bit combinations for the byte enables, allowing 8-, 16-, 24- and 32 bit transfers.

AHB only allows 8-, 16- and 32-bit transfers in a single beat as specified by HSIZE. There is no support for 24-bit transfers.

In addition, the AMBA specification states that all transfers within a burst must be aligned to the address boundary equal to the size of the transfer as specified by HSIZE. This means that 16-bit transfers must start at 16b address boundary. In certain cases (unaligned 16b transaction or 24b transactions), processor splits them into 2 independent transactions on AHB Lite interface. AMBA specification also requires all transfers be aligned to address boundary equal to the size of the transfer.

As described i[nTable](#page-95-0) 27, only 7 combinations are generated by processor on AHB-Lite interface.

Table 27. Mapping Lakemont Bytes Enables to AHB

Note1: Processor does not issue transactions with Non-Contiguous Bytes.

AHB Fabric returns all 0's as data if address is out of bound. On DTCM, when address does not fall into SRAM region, SRAM controller returns data that is programmable via a register. Similarly, on ITCM, when address does not fall into Flash Code or OTP Code regions, Flash controller returns data that is programmable via a register.

11.4 Intel® Quark™ microcontroller D2000 Interrupt Controller (MVIC)

The Intel® Quark™ microcontroller D2000 programmable interrupt controller is based on an extension of the interrupt controller in Intel® Quark™ microcontroller D1000. The MVIC (Intel® Quark™ microcontroller D2000 Interrupt Controller) is configured by default to support 32 external interrupt lines. Unlike the traditional IA LAPIC/IOAPIC, the interrupt vectors in MVIC are fixed and not programmable. In addition, the priorities of these interrupt lines are also fixed. The interrupt vectors corresponding to the 32 interrupt lines respectively are shown in [Table 28.](#page-96-0)

Table 28: MVIC Interrupt Vector Assignment

The higher the vector number, the higher the priority of the interrupt. Higher priority interrupts preempt lower priority interrupts. Lower priority interrupts do not preempt higher priority interrupts. The MVIC holds the lower priority interrupts pending until the interrupt service routine for the higher priority interrupt writes to the End of Interrupt (EOI) register. After an EOI write, the MVIC asserts the next highest pending interrupt.

11.4.1 MVIC Registers

[Table 29](#page-97-0) enumerates all the programmable registers in the MVIC:

Table 29: MVIC registers

11.4.1.1 TPR

- SW writes to this register with a line number to set a priority threshold. The MVIC will not deliver unmasked interrupts with line number lower than the TPR value.
- Since the vectors are fixed, the TPR is programmed with the corresponding interrupt line number (0 to 31). Software should NOT program the vector into the TPR register. The line number to vector mapping is done internal to the MVIC.
- If SW programs the TPR as 32, then all un-masked interrupts will not be delivered.
- Register Description :

11.4.1.2 PPR

The MVIC sets the PPR to either the highest priority pending interrupt in the ISR or the current task priority, whichever is higher.

11.4.1.3 EOI

The EOI is set when CPU initiates a write to address FEE000B0h. Upon receipt of the EOI write, the MVIC clears the highest-priority ISR bit, which corresponds to the interrupt that was just serviced. The MVIC ignores the actual value written to the EOI Register.

11.4.1.4 SIVR

SW writes the vector used for spurious interrupts to the SIVR

11.4.1.5 ISR

This register tracks interrupts that have already requested service to the core but have not yet been acknowledged by SW. The MVIC set the bit in ISR (In-Service Register) after the core recognizers the corresponding interrupt. The bit in the ISR is cleared when SW writes to the EOI register. Bit N corresponds to the interrupt request N for interrupt vectors 32 to 63.

11.4.1.6 IRR

This register contains the active interrupt requests that have been accepted, but not yet dispatched to the core for servicing. When the MVIC accepts an interrupt, it sets the bit in the IRR that corresponds to the vector of the accepted interrupt. When the core is ready to handle the next interrupt, it will sent an INTA cycle and the MVIC clears the highest priority IRR (Interrupt Request Register) bit that is set and sets the corresponding ISR bit. Note that if the interrupt line for the IRR is not cleared, then the IRR bit will NOT be cleared when the INTA is sent by the CPU.

11.4.1.7 LVTTIMER

- Is used to inject an interrupt when the timer inside the MVIC expires.
- In the current implementation, lines 0 to 15 can be used to inject timer interrupts to the CPU.
- SW can programs bits 3-0 of the LVTTIMER register to indicate which interrupt line needs to be converted into a timer interrupt. Based on the line programmed, when the timer expires, the MVIC will inject the corresponding vector (0x20 to 0x2f). This interrupt line must be configured for edge mode.
- Bit 16 is the mask bit
- Bit 17 is the periodic mode bit.

0

11.4.1.8 ICR

- The initial count of the timer. The timer counts down from this value to 0.
- In periodic mode, the timer automatically reloads the Current Count Register (CCR) from the ICR when the count reaches 0. At this time, the MVIC generates a timer interrupt to the core and the countdown repeats.
- If during the countdown process software writes to the ICR, counting restarts using the new initial count value.
- A write of 0 to the ICR effectively stops the local MVIC timer, in both one-shot and periodic mode.
	- o The LVT Timer Register determines the vector number delivered to the core when the timer count reaches zero.
	- o Software can use the mask flag in the LVT timer register to block the timer interrupt.

11.4.1.9 CCR

• The current count of the timer.

• Interrupt lines can be masked/unmasked and the sensitivity (level/edge) can be set by programming the registers found in the I/O controller registers

Software accesses the registers by an indirect addressing scheme using two memory mapped registers, IOREGSEL and IOWIN. Only the IOREGSEL and IOWIN registers are directly accessible in the memory address space. To setup an interrupt, software writes to IOREGSEL with a value specifying the indirect I/O register to be accessed. Software then reads or writes the IOWIN for the desired data from/to the I/O register specified by the index from the IOREGSEL. Software must access the IOWIN register as a dword quantity.

Notes:

• SW can only write to bits 1,2,3,5 and 6 of the IOREGSEL registers. Bits 0 and 4 are reserved. Example : if SW wants to access the IOWIN for index 15 {5'b01111}, then the IOREGSEL register must be programmed with value {6'b01_111_}

• SW can also read the index from the IOREGSEL register through the same bits 1,2,3,5 and 6.

• The IOWIN register has 2 bits per interrupt line (index)

o Bit 16 : Mask

- Trigger: Software sets this bit to configure the interrupt signal as level sensitive. Software clears this bit to configure the interrupt signal as edge sensitive.
- Mask: Software sets this bit to mask the interrupt signal and prevent the MVIC from delivering the interrupt. The MVIC ignores interrupts signaled on a masked interrupt pin and does not deliver nor hold the interrupt pending. Changing the mask bit from unmasked to masked after the MVIC accepts the interrupt has no effect on that interrupt. When this bit is 0, the MVIC does not mask the interrupt and results in the eventual delivery of the interrupt.
- At reset, all interrupts are unmasked.

11.4.2 Programming Sequence

- 1. Initialize GDT
- 2. Initialize IDT
- 3. Initialize MVIC
	- a. Program the respective MVIC registers.
	- b. Program the mask and trigger mode for the 32 interrupt lines through the I/O registers.
- 4. Enables Interrupts to flow (sti)

11.4.3 Interrupt Latency Reduction

- 1. One INTA is issued per interrupt
	- a. LMT-FST issues two INTA cycles
		- b. Validation infrastructure updates required

- 2. The latency for the first interrupt is close to what original LMT has. The latency to deliver subsequent interrupt of the same vector is much improved. The microcode latency is reduced to 21 cycles from 65 cycles.
	- a. This optimization is only enabled in protected ring0 flat mode.
		- i. CS, DS and SS base is 0 and corresponding limits are FFFF_FFFF
	- b. This optimization employs an 32-entry look-aside table
		- i. Entry 0 maps to external interrupt line 0 (vector 32), Entry 1 maps to external interrupt line 1 (vector 33), and so on
		- ii. Each entry contains a valid bit and EIP to corresponding interrupt service routine.
		- iii. EIP to the start of ISR is captured into the interrupt-vector lookaside buffer upon successful delivery of interrupt.
	- c. Invalidation of the interrupt-lookaside buffer is done when :
		- i. LGDT or LIDT instruction is executed
			- ii. Transition to non ring0
		- iii. When the following EFLAGS bits are set: VM, NT, RF and TF
	- d. ISR EIP will **not** be buffered for the following cases. Therefore, the slow interrupt delivery path will be taken if SW does the following
		- i. ISR uses a different CS selector than the CS selector used by the running program that is being interrupted.
		- ii. If the start of ISR is located outside of ITCM Instruction Flash range, i.e. 0x0018_0000 to 0x0018_7FFF.
		- iii. Running in real mode and not in protected mode. In real mode, the IDT is located starting at 0x0000_0000 address.
	- e. SW should use interrupt gate in IDT for ISR. Trap gates for ISR is not supported
	- f. SW should not use 16-bit segment
	- g. All processes running at ring-0 level and allowing interrupts should use the same pair of segments to address instructions and data to take advantage of interrupt fastpath.
	- 3. Requirement:
		- a. If FW modifies IDT or GDT after LIDT or LGDT, FW must execute LIDT or LGDT again.
		- b. If SW wants to use "IRET/far call/far jmp" to change CS and thus descriptor, SW needs to execute LGDT or LIDT to invalidate interruptvector lookaside buffer first.
		- c. SW shall not place the start of ISR in the lowest 256 bytes, i.e. 0x0000_0000 to 0x0000_00FF.

11.4.4 Sample Code

```
Programming timer:
timer = (unsigned int *)0xFEE00320;
 timer_cnt = (unsigned int *)0xFEE00380;
    asm("sti");
// Enable Timer interrupt in Periodic mode using interrupt line 1
   *(timer) = 0x20001;// Timer count
   *(timer_cnt) = 0x200;
Programming I/O IC registers:
          volatile unsigned int *rte;
    volatile unsigned int *index;
    #define LOW_NIBBLE_MASK 0x7
    #define HIGH_NIBBLE_MASK 0x18
   index = (unsigned int *)0xFEC00000;<br>rte = (unsigned int *)0xFEC00010;
                = (unsigned int *)0xFEC00010;
    unsigned int low_nibble;
    unsigned int high_nibble;
// Setting index in the IOREGSEL
   low\_nibble = ((line & LOW\_NIBBLE\_MASK) << 0x1;
    high_nibble = ((line & HIGH_NIBBLE_MASK) << 0x2); 
    *(index) = high_nibble | low_nibble;
// Setting Trigger mode in the IOWIN
   *(rte) = (0x1 \le 15);
```


11.5 CPUID

Note: Return value for EAX = 0x8000_000[2-4] does not contain "D2000" string.

The memory subsystem contains the following volatile and non-volatile memories:

- System Flash 32KB
	-
	- OTP (implemented using Flash Memory) $-8KB + 4 KB$
	- Internal System SRAM 8KB

Each of these regions implement protection mechanisms with access control described later.

12.1 Features

12.1.1 System Flash Controller Features

- The Flash controller interfaces with 32KB Main Memory Block and 8KB of Information Block of Flash memory.
- Supports 64b wide reads via a dedicated Host Processor ITCM Interface.
- Supports 32b wide Instruction reads via an AHB Lite interface. The 32b reads can be performed as single read, incrementing burst or wrapping burst.
- Supports prefetching of programmable number (up to 4) 16B chunks from Flash for requests from AHB interface – prefetching can be enabled/disabled via a configuration register as part of Flash subsystem. There is no prefetching performed on ITCM interface since Processor has its own internal prefetcher.
- Supports page erase via configuration registers in the System Control Module
- Each page is 2KB.
- Supports 32b wide writes via configuration registers in the System Control Module. The procedure for updating Flash is as follows:
	- o Copy Flash Page, with location to be modified, to SRAM

	o Erase the Flash page
	- o Erase the Flash page
o Undate the relevant b
	- Update the relevant bytes in the SRAM copy
	- o Copy the modified page in SRAM into Flash
- Each 32b write operation takes approx. 40us (refer to Flash datasheet $Tnvs(5us) + Tpgs(10us) + Tprog(20us) + Tnvh(5us))$. Supports optional interrupt generation capability after write completion.
- Supports mass erase via configuration registers in the System Control Module.
	- o Only when 4KB OTP has not been programmed. It is the responsibility of FW to prevent Mass Erase when 4KB OTP has been programmed. HW has no built-in protection.
	- o Supports optional interrupt generation capability after erase completion.
- Supports erase reference cell via configuration in the System Control Module this needs to be done to allow reads to work – only needs to be done once in the lifetime of the device.
- Support configurable wait states to allow Flash to run with different frequency clocks. Number of wait states on Flash Read Access as follows:
	- \circ Clk = 4MHz or slower = > 0 wait states supported on first access, 1 wait state on a subsequent access if the second access is on the next clock, 0 wait states on a subsequent access if there is at least a single clock cycle gap after the first access

- \circ Clk = 8MHz = > 1 wait state on all accesses
- o $Clk = 16MHz \Rightarrow 1$ wait state on all accesses
- \circ Clk = 32MHz = > 2 wait states on all accesses

Flash Protection mechanisms: The Flash Read Protection features are as follows:

- There are 2 Agents:
	- o Lakemont (determined by the AHB Master ID)
	- o DMA (determined by the AHB Master ID)
		- Protection mechanism s are the same between the 2 DMA channels.
- Supports a lock-out feature where Flash writes/erases are disabled via a register write. Once Flash writes have been disabled, a warm reset is required to re-enable write access.
- 4 Configurable Flash Protection Regions (FPRs) with addressing of 1KB byte granularity. There is no size restriction for each region. Each region has lower and upper bound addresses - aligned to 1KB boundary, for address range checks. Address used for comparison is offset within 36KB of Main Memory block. With 1KB alignment, only 6b are needed for lower and upper bound address comparison. The mechanism is not applicable to 8KB OTP Code region of system address space.
- The FPRs are disabled by default in this case all Agents have RD & WR access to the whole of the Flash
- Each FPR has a set of programmable Access Control flags described as follows:

- The Access Control flags can be locked when locked they can only be reprogrammed after a Warm Reset
- The Regions may overlap in this scenario ALL of the relevant Access Enables needs to be set to allow an Agent to access that overlapping region (i.e. an AND operation)
- In the event of an Access Violation during a Read Access the data is replaced with value from a config register, and the I/F protocol is handled as for a normal Read Access (the read to Flash is still performed and the read data from Flash is overwritten)
- When an Access Violation occurs, a Violation Event trigger (Interrupt) is asserted and the following information is logged: The Agent, the Address (offset within 36KB Main Memory block) and the Transfer Type (Flash RD)
- There are 2 modes for handling a Violation Event:
	- o Debug Mode the Violation Event is used to trigger Probe Mode on Processor effectively triggering a break point -
	- o Normal Mode the Violation Event is treated as an Interrupt that can be routed to the Processor.

• Support a scan mode where all the Flash control signals are gated during scan.

The FPR registers reside in the Flash Controller Configuration Registers.

The previously described protection is applied for ITCM requests also.

12.1.2 OTP Features

- 8KB OTP:
	- o Implemented using the information memory region of Flash.
	- o Part of Processor's Instruction address space (ITCM).
	- o Supports 64b wide reads via ITCM Interface.
	- o Supports 32 bit wide reads via an AHB Lite Interface.
	- o A Rotated Priority access scheme is used to arbitrate between the ITCM Interface and the AHB Lite Interface.
	- o Write, page erase and erase reference cell supported as per section [12.1.1](#page-105-0) before the region is programmed as OTP.
	- o Wait state behavior as per section [12.1.1](#page-105-0) and same as Code Flash.

	o Supports a hardware lock mechanism to prevent writes to and eras
	- Supports a hardware lock mechanism to prevent writes to and erases of OTP. If bit 0 of offset 0x0 of the information memory region of Flash is 0b, then OTP region is considered programmed and hardware blocks all writes/erases of information memory.
	- o An upper and lower lock bit to disable reads to the upper 4KB and lower 4KB regions of Flash. The register lock bits can only be cleared after a warm reset.
	- o When an Access Violation occurs a Violation Event trigger (Interrupt) is asserted and the following information is logged: The Agent, the Address and the Transfer Type (ROM RD).
	- o Mass Erase capability is disabled by HW once 8KB OTP has been programmed.
- 4KB OTP:
	- o There is a limitation of max 8KB of information memory inside a flash device. Hence, 4KB OTP is implemented using the Main Memory block of Flash. Remaining 32KB of Main Memory block is used for instruction code.
	- o Not part of either of Processor's ITCM or DTCM address spaces and accessed by Processor over AHB-Lite interface.
	- o Transparent to HW and entirely managed by FW using FPR.
	- o Access control is enforced via FPR.
	- o Supports 32 bit wide reads via an AHB Lite Interface.
	- o A Rotated Priority access scheme is used to arbitrate between the ITCM Interface and the AHB Lite Interface.
	- o FW must not issue Mass Erase once 4KB OTP has been programmed.

12.1.3 Internal SRAM Features

- The internal SRAM controller presents 8KB of SRAM organized in the form of 2 banks of 4KB each.
- Supports 64 bit wide reads and writes via a dedicated Host Processor DTCM Interface. Processor only reads and writes 32b at a time. Byte enables indicate which SRAM bank the request is targeting. All accesses are 64b address aligned.
- Supports 32 bit wide reads and writes via an AHB Lite Interface.
- A Rotated Priority access scheme is used to arbitrate between the DTCM Interface and the AHB Lite Interface. The arbitration scheme will result in 0 wait states being applied to the respective interface for arbitration win scenario and 1 wait state being applied to the respective interface for arbitration loss scenario.
- Latency:

Memory Region Protection capabilities are provided by the SRAM controller and apply to accesses originating from both the TCM I/F block and the AHB I/F block. These capabilities are as follows:

- 2 Agents:
	- o Lakemont Data TCM + Lakemont AHB (determined by the AHB Master ID)
	- o DMA
- 4 Configurable Isolated Memory Regions (IMRs) for memory protection with addressing of 1KB byte granularity
- The IMRs are defined by a lower bound and an upper bound, for an address to be within the IMR it must be greater than or equal to the lower bound **and** less than or equal to the upper bound
- The IMRs are disabled by default in this case all Agents have RD & WR access to the whole of the SRAM
- Each IMR has a set of programmable Access Control flags described as follows:

- The Access Control flags can be locked when locked they can only be reprogrammed after a Warm Reset
- The Regions may overlap refer to Figure 9 [Example IMR zones](#page-109-0) Requests that fall in the region overlapped by IMR B and IMR C are **only** allowed if the requesting agent is enabled for **both IMRs**
- In the event of an Access Violation during a Write Access the data is dropped, not written to SRAM and the I/F protocol is handled as for a normal Write Access (the byte enables can be brought low to satisfy this)
- In the event of an Access Violation during a Read Access the data is replaced with Dummy Data, and the I/F protocol is handled as for a normal Read Access (the read to SRAM can still be done to satisfy this with the dummy data over-riding the actual data read from SRAM)
	- o This Dummy Data is programmable and is locked along with the Access Control flags above.

- When an Access Violation occurs a Violation Event trigger (Interrupt) is asserted and the following information is logged: The Agent, the Address and the Transfer Type (RD/WR)
- The Violation Event trigger is output as an interrupt See Interrupt Routing for additional details relating to how this interrupt can be routed.

Figure 10 Example IMR zones

The IMR registers will reside in the SRAM Controller Configuration Registers. In addition, DTCM interface also performs address range checks.

12.2 Error Handling

Behavior of CPU prefetch crossing address boundaries is as follows:

- Case 1: Reset vector fetch from 0xFFFF_FFF0 and 0xFFFF_FFF8 can potentially cause the CPU to prefetch from address 0x0, 0x8 and 0x10
	- o The accesses to 0x0, 0x8, and 0x10 fall in the OTP code region. SoC will return the data from the OTP ROM.
	- o This will NOT be treated as an error condition and No spurious interrupts will be sent to the CPU.

- Case 2: CPU executing from 0x1FFF (end of OTP Instruction ROM). CPU prefetch can spill over to the reserved range 0x2000-0x7_FFFF.
	- o The accesses to the reserved range will be completed. The SoC will return a fixed value of all Cs.
	- o This will NOT be treated as an error condition and No spurious interrupts will be sent to the CPU.
- Case 3: CPU executing from 0x18_7FFF (end of Instruction RAM). CPU prefetch can spill over to the reserved range 0x18_8000-0x1F_FFFF.
	- o The accesses to the reserved range will be completed. The SoC will return a fixed value of all Cs.
	- o This will NOT be treated as an error condition and No spurious interrupts will be sent to the CPU.
- Case 4: CPU executing from 0x20_0FFF (end of Data ROM). CPU prefetch can spill over to the reserved range 0x20_1000-0x27_FFFF.
	- o The accesses to the reserved range will be completed.
	- o Since Data ROM access are sent out on AHB. The AHB fabric will return an error and can inject an interrupt for error notification.
- Case 5: CPU executing from 0x28 1FFF (end of Data RAM). CPU prefetch can spill over to the reserved range 0x28_2000-0x2F_FFFF.
	- o The accesses to the reserved range will be completed. The SoC will return a fixed value of all Cs.
	- Instruction fetches to the Data RAM are sent out on AHB Interface. The AHB fabric will return an error and can inject an interrupt for error notification.
- Case 6: CPU executing from a specific region of Data RAM which is setup via IMR (Isolated Memory Region) registers such that CPU has privileges to execute from that region. CPU prefetch can spill over to adjacent region for which CPU does not have privileges to execute.
	- o The accesses to violated region will complete.
	- o Instruction fetches to the Data RAM are sent out on AHB Interface. SRAM controller will flag an Access Control violation and can inject an interrupt for error notification.

For cases 4, 5 and 6, the recommendation is for firmware to place the code at the start of the Data RAM to avoid these scenarios and the potential spurious interrupts.

12.3 Memory Consistency Analysis

The following illustration is the block diagram of the memory subsystem.

Figure 11 Block Diagram of The Memory Subsystem

From memory consistency analysis perspective, Intel® Quark™ microcontroller D2000 consists of following key IPs:

- 1. ULP Quark CPU core
- 2. Flash Memory & Flash Controlller
- 3. SRAM & SRAM Controlller
- 4. AHB/APB Fabric
- 5. DMA
- 6. Slave Peripherals
- 7. SCSS Configuration Registers
- LMT-ULP:
	- o Pentium x86 ISA
	- o No I\$ or D\$ and hence no need for snoops.
	- o 32b Addressing
	- o C0, C1 and C2 power states
	- o No FPU
	- o No support for Atomic operations
	- o 3 key interfaces:
		- **64b ITCM: Instruction TCM**
			- Address range hardwired see LMT-ULP Address Map later
			- Code Reads to ITCM address range
			- Aggressive prefetcher for instruction fetches

- Wait-state capability
- Fastest access limited by eFlash latency: 2 wait-state $@$ 32MHz
- 64b DTCM: Data TCM
	- Address range hardwired see LMT-ULP Address Map later
	- Reads/Writes to DTCM address range
	- Wait-state capability
- 32b AHB-Lite: Peripheral interface
	- Master on AHB Lite interface
	- No AHB Slave port
	- No bursting capability
	- Code Reads to DTCM address range
	- Data reads/writes to ITCM address range
	- All probe mode accesses are issued on AHB
	- I/O reads/writes are unsupported by the Intel® Quark™ microcontroller D2000. Such transactions are under SW control and aliased to Memory range on AHB-Lite.
	- All transactions are non-posted transactions.
	- Atomic/Locked transactions are issues as regular memory transactions without lock semantics.
- $O (x)$ APIC + LAPIC
	- 32 IRQs
- o Memory Ordering Model
	- Processor Ordered Memory model
	- DTCM reads are allowed to go ahead of writes (to different addresses than reads)
	- All AHB transactions are in program order.
	- Transactions across ITCM and DTCM interfaces have no ordering relationship to each other.
	- Transactions across ITCM and AHB-Lite interfaces have no ordering relationship to each other. In other words, ITCM read transactions can occur concurrently with AHB-Lite reads/writes.
	- All Stores in LMT must be in program order. It implies:
		- Writes on DTCM interface must be in program order.
			- Writes on AHB Lite interface must be in program order.
		- DTCM write (data access) followed by AHB write (data access) must be in program order.
			- o Specifically, the AHB write cannot start until DTCM write completes. An implication of this is that if SoC introduces wait-states on DTCM interface for the write, LMT will not start the AHB write until the DTCM write completes i.e. wait state goes away and SRAM controller accepts the write.
		- AHB write (data access) followed by DTCM write (data access) must be in program order.
			- Similar to previous case. The DTCM write cannot start until AHB write completes. An implication of this is that if SoC introduces wait-states on AHB-Lite interface for the write, LMT will not start the DTCM write until the AHB write completes i.e. AHB fabric gives a response for the write.

- All DTCM writes and UC AHB reads (data accesses) must be in program order.
	- Same as A3 and A4 above except replace AHB write with AHB read.
	- AHB reads that are code accesses (e.g. to SRAM) have no ordering relationship with DTCM writes.
- Inside LMT, there is only a single data access outstanding at any time
- Flash Memory & Flash Controller:
	- o Flash controller has 2 interfaces: ITCM and AHB Slave.
	- o Flash Memory has asynchronous interface i.e. there is no clock input.
	- o Read from embedded Flash memory is similar to a standard SRAM read but with increased latency.
	- o However, there is no write capability to Flash memory that is equivalent to a standard SRAM write.
	- o Flash allows a 32b write to arbitrary location (Program Operation) that takes ~40us (36KB Flash Memory size). There is an optional interrupt generation capability after write completion. However, only a '1' in a cell can be changed to a '0' during a Program operation. The only mechanism to write a '1' to a location is to perform a Page–erase operation (2KB page size in Intel® Quark™ microcontroller D2000) or a Mass erase operation which erases entire flash contents to all 1's. An erase operation lasts for ~20ms duration. There is an optional interrupt generation capability after erase completion.
	- o A Program operation is performed via a sequence of writes to Flash Configuration registers.
		- Write target 32b data content to a register
		- Write target flash address to a register
		- Write to a bit in a control register that triggers the required Program sequence operation.
	- o Flash Configuration registers reside off of AHB fabric sharing the AHB Slave port with Flash Controller/Memory.
	- o There is also an upper bound on how many program operations can be performed to same cell - in between erases.
	- o Flash Memory has a single port and only a single operation can be performed at a time. During flash program or erase operation, flash memory is not accessible during the entire duration.
	- o The AHB Slave port has no write-posting capability.
	- o Flash latency can be changed to optimize latency for different clock frequencies.
- SRAM & SRAM Controller:
	- o SRAM controller has 2 interfaces: DTCM and AHB Slave.
	- o Standard SRAM reads and writes
	- o SRAM Configuration registers reside off of AHB fabric sharing the AHB Slave port with SRAM Controller/Memory.
	- o The AHB Slave port and DTCM interface have no write-posting capability.
- AHB/APB Fabric
	- o No write posting support i.e. all writes are non-posted.
	- o In-order fabric with no pipelining.
	- o Only 2 masters on fabric: LMT and DMA.

- o No locked transaction support.
- o One fabric interface for every master and slave.
- DMA
	- o Separate Master and Slave interfaces on AHB interface
	- o No write posting support i.e. all writes are non-posted.
- Slave Peripherals
	- o Examples: UART, I2C, SPIC, etc.
	- o No write posting support i.e. all writes are non-posted.
	- o Single AHB slave interface to each peripheral.
- **SCSS Configuration Registers**
	- o Control SoC configuration related to Clocks, Power Management, etc.
	- o Reside on AHB fabric on a single AHB slave interface

12.3.1 Producer/Consumer Model Analysis of the Memory Subsystem

Flash Memory is a special case and is discussed later.

From standard Producer/Consumer model perspective, producer produces data, producer writes/triggers flag, consumer reads/receives flag, and consumer consumes data. Goal is to ensure consumer's data is consistent.

- Producers can be: DMA, LMT
- Consumers can be: DMA, LMT
- Data can reside in: SRAM, AHB (DMA/Registers on AHB fabric)
- Flag: LMT Interrupt, SRAM, AHB (DMA/Registers on AHB fabric)

The following scenario combinations are possible and analyzed – some of them are illegal use models but analyzed for completeness.

Write to flash memory write has a very restricted use model. Flash write can be performed for following use cases since SRAM is used for updating run-time data by an application:

- Initialize code (e.g. boot code) after manufacturing,
- Update FW
- Load App

Only LMT can initiate a write to Flash memory via a sequence of register writes to Flash Configuration registers. The only two interesting cases are:

- Handling of SW breakpoint: SW tool chain must perform following sequence of operations:
	- o Copy the appropriate 2K page (that contains the set of instructions to be modified) from Flash memory to SRAM.
	- o Copy the original set of instructions in SRAM to a temporary location (for later restoration) in SRAM
	- o Update 2K page in SRAM with new instructions
	- o Erase the 2KB page in Flash
	- o In a loop, program flash memory 32b at a time.
	- o When the loop completes, flash memory has updated 2K page.

- o Since prefetcher depth is only 128b and a long sequence of operations need to be performed to program flash memory, LMT's prefetcher cannot contain stale instructions.
- Interaction of LMT's instruction prefetcher vs Flash memory updates: From Intel® Quark™ microcontroller D2000's usage model perspective, the routines to program/erase flash memory are part of boot code. It is an illegal usage model to modify this boot code while simultaneously executing from it. Hence, this is not a concern.

12.3.2 Miscellaneous Memory Ordering related Scenarios

Intel® Quark™ microcontroller D2000 has registers on AHB fabric that can alter configurations of various functions of SoC. Some examples are:

• Flash Latency: These fields can be changed by SW to alter flash latency dynamically based on SoC clock frequency.

• Flash Program/Erase operation: Program/Erase is under SW control.

• System Clock/Oscillator Control: SW can power down the main oscillator and go to deep-sleep state only to be woken up by an external wake event via analog comparator input. The wake event requires no SoC clock and it enables the system clock/oscillator.

Since AHB write to above register fields can be concurrent to ITCM code fetches, some form of synchronization is required to ensure ITCM interface is quiesced for these registers to alter SoC operation in a safe manner. It is possible to analyze the above 3 cases and find solutions. But a capability to control ITCM prefetching under specific conditions is a very useful capability that is lacking. One of the solutions is to execute HALT instruction as a following instruction that updates above register fields. Upon completion of HALT instruction, LMT is guaranteed to have made all interfaces idle. The assertion of xhalt signal (output of LMT) can be used as a deterministic mechanism to take effect the new states of registers like above.

12.4 Memory Mapped IO Registers

This section describes IO registers.

12.4.1 Flash Controller 0 Register Summary

MEM BaseAddress: 0xB0100000

12.4.2 Flash Controller 0 Register Detailed Description

12.4.2.1 TMG_CTRL (TMG_CTRL)

Flash Timing Control Register. There is a SW programming restriction for this register. When switching SoC to a higher frequency, this register must be updated first to reflect settings associated with higher frequency **BEFORE** SoC frequency is changed. On the other hand, when switching SoC to a lower frequency, this register must be updated only 6 NOP instructions **AFTER** the SoC frequency has been updated. Otherwise, flash timings will be violated.

READ_WAIT_STATE_L and MICRO_SEC_CNT are optimized for 32MHz. These settings are conservative for lower frequency and add access latency for reads. But functionally, these settings will work for any frequency \langle = 32MHz for reads. For program/erase operations, default value of MICRO_SEC_CNT will violate flash timings at < 32MHz frequency. Hence, MICRO_SEC_CNT must be changed before flash can be programmed/erased at non-32MHz frequency.

> **Size** 32 bits **Default** 0000_0060h

12.4.2.2 ROM_WR_CTRL (ROM_WR_CTRL)

ROM Write Control Register

This register is only applicable for 8KB OTP region. There is no equivalent register for 4KB OTP region.

Before issuing flash erase/program operation,

- 1. FW must disable all interrupts except the flash interrupt that indicates completion of erase/program operation.
- 2. Issue the MMIO write that triggers the program or erase operation.
- 3. Issue HALT instruction.

As part of program/erase completion ISR, interrupts can be re-enabled.

12.4.2.3 ROM_WR_DATA (ROM_WR_DATA)

ROM Write Data

This register is only applicable for 8KB OTP region. There is no equivalent register for 4KB OTP region.

MEM Offset (B0100000) 8h **Security_PolicyGroup IntelRsvd** False False False False **Size** 32 bits

0000_0000h

12.4.2.4 FLASH_WR_CTRL (FLASH_WR_CTRL)

Flash Write Control Register

Before issuing flash erase/program operation,

1. FW must disable all interrupts except the flash interrupt that indicates completion of erase/program operation.

- 2. Issue the MMIO write that triggers the program or erase operation.
- 3. Issue HALT instruction.

As part of program/erase completion ISR, interrupts can be re-enabled.

12.4.2.5 FLASH_WR_DATA (FLASH_WR_DATA)

Flash Write Data

12.4.2.6 FLASH_STTS (FLASH_STTS)

Flash Status

12.4.2.7 CTRL (CTRL)

Control Register ROM below refers to 8KB OTP region only.

12.4.2.8 FPR0_RD_CFG (FPR0_RD_CFG)

12.4.2.9 FPR1_RD_CFG (FPR1_RD_CFG)

12.4.2.10 FPR2_RD_CFG (FPR2_RD_CFG)

12.4.2.11 FPR3_RD_CFG (FPR3_RD_CFG)

12.4.2.12 MPR_WR_CFG (MPR_WR_CFG)

Flash Write Protection Control Register

This register is unused in HW and serves no purpose.

12.4.2.13 MPR_VSTS (MPR_VSTS)

Protection Status Register

MEM Offset (B0100000) 30h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0000h

12.4.2.14 MPR_VDATA (MPR_VDATA)

Memory Protection Region Violation Data Value

12.4.3 Internal SRAM Register Summary

MEM BaseAddress: 0xB0400000

12.4.4 Internal SRAM Register Detailed Description

12.4.4.1 MPR_CFG (MPR0_CFG)

Memory Protection Region Configuration Register

12.4.4.2 MPR_CFG (MPR1_CFG)

Memory Protection Region Configuration Register

12.4.4.3 MPR_CFG (MPR2_CFG)

Memory Protection Region Configuration Register

12.4.4.4 MPR_CFG (MPR3_CFG)

Memory Protection Region Configuration Register

Size 32 bits **Default** 0000_0000h

12.4.4.5 MPR_VDATA (MPR_VDATA)

Memory Protection Region Violation Data Value

12.4.4.6 MPR_VSTS (MPR_VSTS)

Memory Protection Region Violation Details

13 I2C

The SoC implements one instance of an I²C controller, which can operate in master mode or slave mode as configured. Both 7 bit and 10 bit addressing modes are supported.

13.1 Signal Descriptions

Please see Chapter [2,](#page-20-0) ["Physical Interfaces"](#page-20-0) for additional details.

The signal description table has the following headings:

- **Signal Name:** The name of the signal/pin
- **Direction:** The buffer direction can be either input, output, or I/O (bidirectional)
- **Type:** The buffer type found in Chapter [4,](#page-39-0) ["Electrical Characteristics"](#page-39-0)
- Description: A brief explanation of the signal's function

Table 30. [Memory 0](#page-105-0) Signals

The following is a list of the I²C features:

13.2 Features

- One I²C Interface
- Support both Master and Slave operation
- Operational Speeds:
	- o Standard Mode (0 to 100 Kbps)
	- o Fast Mode (≤ 400 Kbps)
	- o Fast Mode Plus (≤ 1 Mbps)
- 7 bit or 10 bit Addressing
- Supports Clock Stretching by Slave Devices
- Multi-Master Arbitration
- Spike Suppression

- Hardware Handshake Interface to support DMA capability
- Interrupt Control
- FIFO support with 16B deep RX and TX FIFO's

13.3 Memory Mapped IO Registers

Registers listed are for I2C 0, starting at base address B0002800h.

Table 31. Summary of I2C Registers—0xB0002800

13.3.1.1 Control Register (IC_CON)

Used to control the I2C controller. Can be written only when the I2C is disabled (IC_ENABLE=0). Writes at other times have no effect.

MEM Offset () 0B0002800h **Security_PolicyGroup IntelRsvd** False Factor False Factor False False Factor Facto **Size** 32 bits

Default 0000_007Fh

13.3.1.2 Master Target Address (IC_TAR)

Can be written only when the I2C is disabled (IC_ENABLE==0). Writes at other times have no effect.

MEM Offset () 0B0002804h **Security_PolicyGroup IntelRsvd** False Factor False **Default** 0000_2055h

Size 32 bits

13.3.1.3 Slave Address (IC_SAR)

Holds the slave address when the I2C is operating as a slave. Can be written only when the I2C is disabled (IC_ENABLE==0). Writes at other times have no effect

MEM Offset () 0B0002808h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0055h

13.3.1.4 High Speed Master ID (IC_HS_MADDR)

I2C High Speed Master Mode Code Address. Can be written only when the I2C is disabled $(IC_ENABLE==0)$. Writes at other times have no effect.

13.3.1.5 Data Buffer and Command (IC_DATA_CMD)

CPU writes to it when filling the TX FIFO and the reads from when retrieving bytes from RX FIFO.

13.3.1.6 Standard Speed Clock SCL High Count (IC_SS_SCL_HCNT)

Sets the SCL clock high-period count for standard speed (SS). Can be written only when the I2C is disabled (IC_ENABLE==0). Writes at other times have no effect.

MEM Offset () 0B0002814h **Security_PolicyGroup IntelRsvd** False Factor False **Size** 32 bits

Default 0000_0190h

I2C

13.3.1.7 Standard Speed Clock SCL Low Count (IC_SS_SCL_LCNT)

Sets the SCL clock low-period count for standard speed (SS). Can be written only when the I2C is disabled (IC_ENABLE==0). Writes at other times have no effect.

MEM Offset () 0B0002818h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_01D6h

13.3.1.8 Fast Speed Clock SCL High Count (IC_FS_SCL_HCNT)

Sets the SCL clock high-period count for fast speed (FS). Can be written only when the I2C is disabled (IC_ENABLE==0). Writes at other times have no effect.

13.3.1.9 Fast Speed I2C Clock SCL Low Count (IC_FS_SCL_LCNT)

Sets the SCL clock low-period count for fast speed (FS). Can be written only when the I2C is disabled (IC_ENABLE==0). Writes at other times have no effect.

MEM Offset () 0B0002820h **Security_PolicyGroup IntelRsvd** False Factor False **Size** 32 bits

Default 0000_0082h

13.3.1.10 High Speed I2C Clock SCL High Count (IC_HS_SCL_HCNT)

Sets the SCL clock high-period count for high speed (HS). Can be written only when the I2C is disabled (IC_ENABLE==0). Writes at other times have no effect.

MEM Offset () 0B0002824h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0006h

13.3.1.11 High Speed I2C Clock SCL Low Count (IC_HS_SCL_LCNT)

Sets the SCL clock low-period count for high speed (HS). Can be written only when the I2C is disabled (IC_ENABLE==0). Writes at other times have no effect.

MEM Offset () 0B0002828h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0010h

I2C

13.3.1.12 Interrupt Status (IC_INTR_STAT)

Each bit in this register has a corresponding mask bit in the IC_INTR_MASK register. These bits are cleared by reading the matching interrupt clear register. The unmasked raw versions of these bits are available in the IC_RAW_INTR_STAT register.

13.3.1.13 Interrupt Mask (IC_INTR_MASK)

These bits mask their corresponding interrupt status bits. They are active high; a value of 0 prevents a bit from generating an interrupt.

MEM Offset () 0B0002830h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Default** 0000_18FFh

Size 32 bits

13.3.1.14 Raw Interrupt Status (IC_RAW_INTR_STAT)

Unlike the IC_INTR_STAT register, these bits are not masked so they always show the true status of the I2C controller.

13.3.1.15 Receive FIFO Threshold Level (IC_RX_TL)

Controls the level of entries (or above) that triggers the RX_FULL interrupt (bit 2 in IC_RAW_INTR_STAT register).

13.3.1.16 Transmit FIFO Threshold Level (IC_TX_TL)

Controls the level of entries (or below) that trigger the TX_EMPTY interrupt (bit 4 in IC_RAW_INTR_STAT register).

13.3.1.17 Clear Combined and Individual Interrupt (IC_CLR_INTR)

Read this register to clear the combined interrupt, all individual interrupts, and the IC_TX_ABRT_SOURCE register.

13.3.1.18 Clear RX_UNDER Interrupt (IC_CLR_RX_UNDER)

Clear a single interrupt type.

MEM Offset () 0B0002844h **Security_PolicyGroup IntelRsvd** False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

13.3.1.19 Clear RX_OVER Interrupt (IC_CLR_RX_OVER)

Clear a single interrupt type.

MEM Offset () 0B0002848h **Security_PolicyGroup IntelRsvd** False Factor Factor False Factor False False Factor Facto **Size** 32 bits

Default 0000_0000h

13.3.1.20 Clear TX_OVER Interrupt (IC_CLR_TX_OVER)

Clear a single interrupt type.

MEM Offset () 0B000284Ch **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

Default 0000_0000h

13.3.1.21 Clear RD_REQ Interrupt (IC_CLR_RD_REQ)

Clear a single interrupt type.

13.3.1.22 Clear TX_ABRT Interrupt (IC_CLR_TX_ABRT)

Clear a single interrupt type.

MEM Offset () 0B0002854h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0000h

13.3.1.23 Clear RX_DONE Interrupt (IC_CLR_RX_DONE)

Clear a single interrupt type.

13.3.1.24 Clear ACTIVITY Interrupt (IC_CLR_ACTIVITY)

Clear a single interrupt type.

MEM Offset () 0B000285Ch **Security_PolicyGroup IntelRsvd** False
 Size 32 bit **Default** 0000_0000h

Size 32 bits

13.3.1.25 Clear STOP_DET Interrupt (IC_CLR_STOP_DET)

Clear a single interrupt type.

MEM Offset () 0B0002860h **Security_PolicyGroup IntelRsvd** False Factor False **Default** 0000_0000h

Size 32 bits

13.3.1.26 Clear START_DET Interrupt (IC_CLR_START_DET)

Clear a single interrupt type.

MEM Offset () 0B0002864h **Security_PolicyGroup IntelRsvd** False Factor False **Size** 32 bits

Default 0000_0000h

13.3.1.27 Clear GEN_CALL Interrupt (IC_CLR_GEN_CALL)

Clear a single interrupt type.

13.3.1.28 Enable (IC_ENABLE)

Controls whether the I2C controller is enabled. Software can disable I2C controller while it is active.

13.3.1.29 Status (IC_STATUS)

Read-only register used to indicate the current transfer status and FIFO status. The status register may be read at any time. None of the bits in this register request an interrupt. When the I2C is disabled by writing 0 in bit 0 of the IC_ENABLE register: bits 1 and 2 are set to 1, bits 3 and 4 are set to 0.

When the master or slave state machines goes to idle and IC_EN=0: bits 5 and 6 are set to 0.

13.3.1.30 Transmit FIFO Level (IC_TXFLR)

Contains the number of valid data entries in the transmit FIFO buffer. It is cleared whenever: The I2C is disabled, there is a transmit abort (i.e. TX_ABRT bit is set in the IC_RAW_INTR_STAT register) or the slave bulk transmit mode is aborted.

The register increments whenever data is placed into the transmit FIFO and decrements when data is taken from the transmit FIFO.

13.3.1.31 Receive FIFO Level (IC_RXFLR)

This register contains the number of valid data entries in the receive FIFO buffer. It is cleared whenever: The I2C is disabled, whenever there is a transmit abort caused by any of the events tracked in IC_TX_ABRT_SOURCE. The register increments whenever data is placed into the receive FIFO and decrements when data is taken from the receive FIFO.

13.3.1.32 SDA Hold (IC_SDA_HOLD)

This register controls the amount of hold time on the SDA signal after a negative edge of SCL line in units of I2C clock period. The value programmed must be greater than the minimum hold time in each mode for the value to be implemented: 1 cycle in master, 7 cycles in slave mode. Writes to this register succeed only when I2C controller is disabled (IC_ENABLE=0).

13.3.1.33 Transmit Abort Source (IC_TX_ABRT_SOURCE)

Used to indicate the source of the TX_ABRT interrupt. Except for Bit 9, this register is cleared whenever the IC_CLR_TX_ABRT register or the IC_CLR_INTR register is read. To clear Bit 9, the source of the ABRT_SBYTE_NORSTRT must be fixed first; RESTART must be enabled (IC_CON[5]=1), the SPECIAL bit must be cleared (IC_TAR[11]), or the GC_OR_START bit must be cleared (IC_TAR[10]). Once the source of the ABRT_SBYTE_NORSTRT is fixed, then this bit can be cleared in the same manner as other bits in this register. If the source of the ABRT_SBYTE_NORSTRT is not fixed before attempting to clear this bit, Bit 9 clears for one cycle and is then re-asserted.

13.3.1.34 SDA Setup (IC_DMA_CR)

The register is used to enable the DMA Controller interface operation. There is a separate bit for transmit and receive. This can be programmed regardless of the state of IC_ENABLE.

MEM Offset () 0B0002888h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

13.3.1.35 DMA Transmit Data Level Register (IC_DMA_TDLR)

MEM Offset () 0B000288Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0000h

13.3.1.36 I2C Receive Data Level Register (IC_DMA_RDLR)

MEM Offset () 0B0002890h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

13.3.1.37 SDA Setup (IC_SDA_SETUP)

Controls the amount of time delay (in terms of number of I2C clock periods) introduced in the rising edge of SCL relative to SDA changing, by holding SCL low when servicing a read request while operating as a slave-transmitter. This register must be programmed with a value equal to or greater than 2.

MEM Offset () 0B0002894h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Default** 0000_0064h

Size 32 bits

13.3.1.38 General Call Ack (IC_ACK_GENERAL_CALL)

Controls whether the I2C controller responds with a ACK or NACK when it receives an I2C General Call address.

13.3.1.39 Enable Status (IC_ENABLE_STATUS)

Report the I2C hardware status.

MEM Offset () 0B000289Ch **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

13.3.1.40 SS and FS Spike Suppression Limit (IC_FS_SPKLEN)

Used to store the duration, measured in I2C clock cycles, of the longest spike that is filtered out by the spike suppression logic when the component is operating in Standard/Fast Speed modes. The relevant I2C requirement is detailed in the I2C Bus Specification. This register must be programmed with a minimum value of 2.

MEM Offset () 0B00028A0h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

13.3.1.41 HS spike suppression limit (IC_HS_SPKLEN)

Used to store the duration, measured in I2C clock cycles, of the longest spike that is filtered out by the spike suppression logic when the component is operating in High Speed mode. This register must be programmed with a minimum value of 2.

13.3.1.42 Clear the RESTART_DET interrupt (IC_CLR_RESTART_DET)

Read this register to clear the RESTART_DET interrupt.

13.3.1.43 Configuration Parameters (IC_COMP_PARAM_1)

Contains encoded information about the component's parameter settings.

Register Offset 0B00028F4h **IntelRsvd**
Size **Size** 32 bits **PowerWell**

Default 000F_0FAEh

13.3.1.44 Component Version (IC_COMP_VERSION)

13.3.1.45 Component Type (IC_COMP_TYPE)

14 UART

The SoC implements two instances of a 16550 compliant UART controller that supports baud rates between 300 baud and 2M baud. Hardware flow control is also supported. Both RS232 and RS485 are supported. 9-bit mode is also supported.

14.1 Signal Descriptions

Table 33. [Memory](#page-105-0) 1 or UART B Signals

14.2 Features

Both UART instances are configured identically, the following is a list of the UART controller features:

- Operation compliant with the 16550 Standard
	- o Start bit
	- o 5 to 9 bits of Data
	- o Optional Parity bit (Odd or Even)
	- \circ 1, 1.5 or 2 Stop bits
- Baud Rate configurability between 300 baud and 2M baud.
	- o Maximum baud rate is limited by system clock frequency divided by 16.
	- o Supported baud rates: 300, 1200, 2400, 4800, 9600, 14400, 19200, 38400, 57600, 76800, 115200; multiples of 38.4kbps and multiples of 115.2kbps upto 2M baud
- Auto Flow Control mode as specified in the 16750 Standard
- Hardware Flow Control
- Software Flow Control (when Hardware Flow Control is disabled)
- Hardware Handshake Interface to support DMA capability
- Interrupt Control
- FIFO support with 16B TX and RX FIFO's
- Support of RS485
	- o Differential driver/receiver is external to SoC.
		- o Driver enable (DE) and Receiver enable (RE) outputs are driven from SoC to control the differential driver/receiver.
- Fractional clock divider that ensures less than 2% frequency error for most supported baud rates.
	- o Fraction resolution is 4-bits.
	- o Exception: 2.07% error for 1.391 Mbaud, 2.12% for 1.882 Mbaud and 2Mbaud, 2.53% error for 1.684 Mbaud.
- 9-bit data transfer mode to support multi-drop system where one master is connected to multiple slaves in a system

14.3 Memory Mapped IO Registers

Registers listed are for UART 0 or UART A, starting at base address B0002000h. UART 1 or UART B contains the same registers starting at base address B0002400h. Differences between the UARTs are noted in individual registers.

Table 34. Summary of UART Registers—0xB0002000

14.3.1.1 Receive Buffer / Transmit Holding / Divisor Latch Low (RBR_THR_DLL)

Receive Buffer Register(RBR), reading this register when the DLAB bit (LCR[7]) is zero; Transmit Holding Register (THR), writing to this register when the DLAB is zero; Divisor Latch Low (DLL), when DLAB bit is one.

MEM Offset (B0002000) 0B0002000h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

14.3.1.2 Interrupt Enable / Divisor Latch High (IER_DLH)

Interrupt Enable Register (IER), when the DLAB bit is zero; Divisor Latch High (DLH), when the DLAB bit is one.

MEM Offset (B0002000) 0B0002004h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

14.3.1.3 Interrupt Identification / FIFO Control (IIR_FCR)

Interrupt Identification Register (IIR) if reading; FIFO Control Register (FCR) if writing.

MEM Offset (B0002000) 0B0002008h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

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14.3.1.4 Line Control (LCR)

Used to specify the format of the asynchronous data communication exchange.

MEM Offset (B0002000) 0B000200Ch **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

14.3.1.5 MODEM Control (MCR)

Controls the interface with the MODEM or data set (or a peripheral device emulating a MODEM).

MEM Offset (B0002000) 0B0002010h

Size 32 bits **Default** 0000_0000h

14.3.1.6 Line Status (LSR)

Provides status information concerning the data transfer.

14.3.1.7 MODEM Status (MSR)

Provides the current state of the control lines from the MODEM (or peripheral device).

MEM Offset (B0002000) 0B0002018h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

14.3.1.8 Scratchpad (SCR)

Used by the programmer to hold data temporarily.

MEM Offset (B0002000) 0B000201Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

14.3.1.9 UART Status (USR)

Provides internal status information.

MEM Offset (B0002000) 0B000207Ch **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

14.3.1.10 Halt Transmission (HTX)

Halt Transmission.

14.3.1.11 DMA Software Acknowledge (DMASA)

DMA software acknowledge if a transfer needs to be terminated due to an error condition.

14.3.1.12 Transceiver Control Register (TCR)

Transceiver Control Register.

MEM Offset (B0002000) 0B00020ACh **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits **Default** 0000_0006h

14.3.1.13 Driver Output Enable Register (DE_EN)

Driver Output Enable Register.

MEM Offset (B0002000) 0B00020B0h **Security_PolicyGroup** IntelRsvd False **Size** 32 bits

14.3.1.14 Receiver Output Enable Register (RE_EN)

Receiver Output Enable Register.

MEM Offset (B0002000) 0B00020B4h **Security_PolicyGroup IntelRsvd** False False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

14.3.1.15 Driver Output Enable Timing Register (DET)

Used to holds the DE assertion and de-assertion timings of the signal.

MEM Offset (B0002000) 0B00020B8h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

14.3.1.16 TurnAround Timing Register (TAT)

TurnAround Timing Register.

MEM Offset (B0002000) 0B00020BCh **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

14.3.1.17 Divisor Latch Fraction (DLF)

Divisor Latch Fraction.

MEM Offset (B0002000) 0B00020C0h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

Default 0000_0000h

14.3.1.18 Receive Address Register (RAR)

Receive Address Register.

MEM Offset (B0002000) 0B00020C4h **Security_PolicyGroup IntelRsvd** False False False 32 bit **Size** 32 bits

14.3.1.19 Transmit Address Register (TAR)

Transmit Address Register.

MEM Offset (B0002000) 0B00020C8h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

14.3.1.20 Line Extended Control Register (LCR_EXT)

Line Extended Control Register.

MEM Offset (B0002000) 0B00020CCh **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor Fact **Size** 32 bits

15 SPI

The SoC implements two instances of a SPI controller. One controller supports Master operation and another controller supports Slave operation.

15.1 Signal Descriptions

Please see Chapter [2,](#page-20-0) ["Physical Interfaces"](#page-20-0) for additional details.

The signal description table has the following headings:

- **Signal Name:** The name of the signal/pin
- **Direction:** The buffer direction can be either input, output, or I/O (bidirectional)
- **Type:** The buffer type found in Chapter [4,](#page-39-0) ["Electrical Characteristics"](#page-39-0)
- **Description:** A brief explanation of the signal's function

Table 35. SPI Master 0 Signals

Table 36. SPI Slave 0 Signals

NOTE: Signal Names are preliminary and are subject to changes when the "Physical Interfaces" Chapter is populated.

15.2 Features

The following is a list of the SPI Master features:

- One SPI Master Interface
- Control of up to 4 Slave Selects
- Frame Formats:
	- o Motorola SPI*
- Transfer Modes:
	- o Transmit & Receive
	- o Transmit Only
	- o Receive Only
	- o EEPROM Read
- Serial Clock Frequencies up to 16 MHz
- 4 bit to 32 bit Frame Size
- Configurable Clock Polarity and Clock Phase
- Hardware Handshake Interface to support DMA capability
- Interrupt Control
- FIFO mode support with 8B deep TX and RX FIFO's

The following is a list of the SPI Slave features:

- One SPI Slave Interface
- Frame Formats:
	- o Motorola SPI*
- Transfer Modes:
	- o Transmit & Receive
	- o Transmit Only
	- o Receive Only
	- o EEPROM Read
- Serial Clock Frequencies up to 3.2 MHz
- 4 bit to 32 bit Frame Size
- Configurable Clock Polarity and Clock Phase
- Hardware Handshake Interface to support DMA capability
- Interrupt Control
- FIFO mode support with 8B deep TX and RX FIFO's

15.3 Memory Mapped IO Registers

Registers listed are for SPI Master 0, starting at base address B0001000h. SPI Slave 0 contains the same registers starting at base address B0001800h. Differences between the SPIs are noted in individual registers.

Table 37. Summary of SPI Registers—0xB0001000 & 0xB0001800

15.3.1.1 Control Register 0 (CTRLR0)

This register controls the serial data transfer. It is impossible to write to this register when the SPI Controller is enabled. The SPI Controller is enabled and disabled by writing to the SSIENR register.

> **Size** 32 bits **Default** 0007_0000h

15.3.1.2 Control Register 1 (CTRLR1)

This register exists only when the SPI Controller is configured as a master device. When the SPI Controller is configured as a serial slave, writing to this location has no effect; reading from this location returns 0. Control register 1 controls the end of serial transfers when in receive-only mode. It is impossible to write to this register when the SPI Controller is enabled. The SPI Controller is enabled and disabled by writing to the SSIENR register.

15.3.1.3 SSI Enable Register (SSIENR)

15.3.1.4 Microwire Control Register (MWCR)

This register controls the direction of the data word for the half-duplex Microwire serial protocol. It is impossible to write to this register when the SPI Controller is enabled. The SPI Controller is enabled and disabled by writing to the SSIENR register.

MEM Offset (B0001000) 0Ch **Security_PolicyGroup IntelRsvd** False
 Size 32 bit **Default** 0000_0000h

15.3.1.5 Slave Enable Register (SER)

This register is valid only when the SPI Controller is configured as a master device. When the SPI Controller is configured as a serial slave, writing to this location has no effect; reading from this location returns 0. The register enables the individual slave select output lines from the SPI Controller master. Up to 16 slave-select output signals are available on the SPI Controller master. You cannot write to this register when SPI Controller is busy.

15.3.1.6 Baud Rate Select (BAUDR)

This register is valid only when the SPI Controller is configured as a master device. When the SPI Controller is configured as a serial slave, writing to this location has no effect; reading from this location returns 0. The register derives the frequency of the serial clock that regulates the data transfer. The 16-bit field in this register defines the ssi_clk divider value. It is impossible to write to this register when the SPI Controller is enabled. The SPI Controller is enabled and disabled by writing to the SSIENR register.

15.3.1.7 Transmit FIFO Threshold Level (TXFTLR)

This register controls the threshold value for the transmit FIFO memory. The SPI Controller is enabled and disabled by writing to the SSIENR register.

15.3.1.8 Receive FIFO Threshold Level (RXFTLR)

This register controls the threshold value for the receive FIFO memory. The SPI Controller is enabled and disabled by writing to the SSIENR register.

15.3.1.9 Transmit FIFO Level Register (TXFLR)

15.3.1.10 Receive FIFO Level Register (RXFLR)

15.3.1.11 Status Register (SR)

This is a read-only register used to indicate the current transfer status, FIFO status, and any transmission/reception errors that may have occurred. The status register may be read at any time. None of the bits in this register request an interrupt.

MEM Offset (B0001000) 28h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Default** 0000_0006h

15.3.1.12 Interrupt Mask Register (IMR)

This read/write register masks or enables all interrupts generated by the SPI Controller.

15.3.1.13 Interrupt Status Register (ISR)

This register reports the status of the SPI Controller interrupts after they have been masked.

15.3.1.14 Raw Interrupt Status Register (RISR)

This register reports the status of the SPI Controller interrupts prior to masking

MEM Offset (B0001000) 34h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

15.3.1.15 Transmit FIFO Overflow Interrupt Clear Register (TXOICR)

Size 32 bits **Default** 0000_0000h

15.3.1.16 Receive FIFO Overflow Interrupt Clear Register (RXOICR)

MEM Offset (B0001000) 3Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

15.3.1.17 Receive FIFO Underflow Interrupt Clear Register (RXUICR)

15.3.1.18 Multi-Master Interrupt Clear Register (MSTICR)

MEM Offset (B0001000) 44h **Security_PolicyGroup IntelRsvd** False Factor False Factor Factor False Factor False Factor Factor Factor Factor Factor Factor Factor Factor Factor Facto **Size** 32 bits

15.3.1.19 Interrupt Clear Register (ICR)

15.3.1.20 DMA Control Register (DMACR)

The register is used to enable the DMA Controller interface operation.

MEM Offset (B0001000) 4Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

15.3.1.21 DMA Transmit Data Level (DMATDLR)

15.3.1.22 DMA Receive Data Level (DMARDLR)

MEM Offset (B0001000) 54h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

15.3.1.23 Identification Register (IDR)

This read-only register is available for use to store a peripheral identification code.

Default 0000_0000h

15.3.1.24 coreKit Version ID register (SSI_COMP_VERSION)

This read-only register stores the specific SPI Controller component version.

15.3.1.25 Data Register (DR0)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.26 Data Register (DR1)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

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15.3.1.27 Data Register (DR2)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.28 Data Register (DR3)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.29 Data Register (DR4)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.30 Data Register (DR5)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

Size 32 bits

MEM Offset (B0001000) 74h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Default** 0000_0000h

15.3.1.31 Data Register (DR6)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.32 Data Register (DR7)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.33 Data Register (DR8)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

Size 32 bits

MEM Offset (B0001000) 80h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Default** 0000_0000h

Bits Access Type Default Description PowerWell ResetSignal 31:16 RO 16'b0 **Reserved 1 (RSVD1)** Reserved 15:0 RW 16'h0 **Data Register (DR)** When writing to this register, you must right-justify the data. Read data are automatically rightjustified. Read = Receive FIFO buffer Write = Transmit FIFO buffer

15.3.1.34 Data Register (DR9)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.35 Data Register (DR10)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.36 Data Register (DR11)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

MEM Offset (B0001000) 8Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0000h

15.3.1.37 Data Register (DR12)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.38 Data Register (DR13)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.39 Data Register (DR14)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

Size 32 bits

MEM Offset (B0001000) 98h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Default** 0000_0000h

Bits Access Type Default Description PowerWell ResetSignal 31:16 RO 16'b0 **Reserved 1 (RSVD1)** Reserved 15:0 RW 16'h0 **Data Register (DR)** When writing to this register, you must right-justify the data. Read data are automatically rightjustified. Read = Receive FIFO buffer Write = Transmit FIFO buffer

15.3.1.40 Data Register (DR15)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when $SSI_EN = 1$. FIFOs are reset when $SSI_EN = 0$.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory

map to facilitate AHB burst transfers. Writing to any of these address locations has the same

effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of

these locations has the same effect as popping data from the receive FIFO onto the prdata

bus. The FIFO buffers on the SPI Controller are not addressable.

MEM Offset (B0001000) 9Ch **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

Default 0000_0000h

15.3.1.41 Data Register (DR16)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when $SSI_EN = 1$. FIFOs are reset when $SSI_EN = 0$.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.42 Data Register (DR17)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when $SSI_EN = 1$. FIFOs are reset when $SSI_EN = 0$.

15.3.1.43 Data Register (DR18)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI $= 1$. FIFOs are reset when SSI $= 0$.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

MEM Offset (B0001000) A8h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0000h

15.3.1.44 Data Register (DR19)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.45 Data Register (DR20)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.46 Data Register (DR21)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

MEM Offset (B0001000) B4h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Default** 0000_0000h

Size 32 bits

15.3.1.47 Data Register (DR22)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.48 Data Register (DR23)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.49 Data Register (DR24)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

Size 32 bits

MEM Offset (B0001000) C0h **Security_PolicyGroup IntelRsvd** False False
Size 32 bit **Default** 0000_0000h

Bits Access Type Default Description PowerWell ResetSignal 31:16 RO 16'b0 **Reserved 1 (RSVD1)** Reserved 15:0 RW 16'h0 **Data Register (DR)** When writing to this register, you must right-justify the data. Read data are automatically rightjustified. Read = Receive FIFO buffer Write = Transmit FIFO buffer

15.3.1.50 Data Register (DR25)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.51 Data Register (DR26)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.52 Data Register (DR27)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

MEM Offset (B0001000) CCh **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Default** 0000_0000h

Size 32 bits

15.3.1.53 Data Register (DR28)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.54 Data Register (DR29)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.55 Data Register (DR30)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

MEM Offset (B0001000) D8h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Default** 0000_0000h

Size 32 bits

15.3.1.56 Data Register (DR31)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.57 Data Register (DR32)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.58 Data Register (DR33)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

Size 32 bits

MEM Offset (B0001000) E4h **Security_PolicyGroup IntelRsvd** False False
Size 32 bit **Default** 0000_0000h

Bits Access Type Default Description PowerWell ResetSignal 31:16 RO 16'b0 **Reserved 1 (RSVD1)** Reserved 15:0 RW 16'h0 **Data Register (DR)** When writing to this register, you must right-justify the data. Read data are automatically rightjustified. Read = Receive FIFO buffer Write = Transmit FIFO buffer

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15.3.1.59 Data Register (DR34)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

NOTE : The DR register in the SPI Controller occupies thirty-six 32-bit address locations of the memory map to facilitate AHB burst transfers. Writing to any of these address locations has the same effect as pushing the data from the pwdata bus into the transmit FIFO. Reading from any of these locations has the same effect as popping data from the receive FIFO onto the prdata bus. The FIFO buffers on the SPI Controller are not addressable.

15.3.1.60 Data Register (DR35)

The SPI Controller data register is a 16-bit read/write buffer for the transmit/receive FIFOs. When the register is read, data in the receive FIFO buffer is accessed. When it is written to, data are moved into the transmit FIFO buffer; a write can occur only when SSI = 1. FIFOs are reset when SSI = 0.

15.3.1.61 RX Sample Delay Register (RX_SAMPLE_DLY)

This register controls the number of ssi_clk cycles that are delayed,from the default sample time, before the actual sample of the rxd input signal occurs. It is impossible to write to this register when the SPI Controller is enabled; the SPI Controller is enabled and disabled by writing to the SSIENR register.

16 DMA Controller

The SoC contains a single 2-Channel DMA controller. The DMA controller supports Single or Multi-Block transfers from Memory to Memory, Peripheral to Memory, Memory to Peripheral or Peripheral to Peripheral.

16.1 Features

The following is a list of the DMA Controller features:

- 2 Unidirectional Channels
- Configurable Channel Prioritization
- Software Handshaking
- Hardware Handshaking Interfaces
- Configurable Transfer Type and Flow Control
- Supports Single-Block Transfers
- Supports Multi-Block Transfers
- Scatter-Gather
- Interrupt Generation per Channel:
	- o DMA Transfer Complete
	- o Block Transfer Complete
	- o Source Transaction Complete
	- o Destination Transaction Complete
	- o Error Response

16.2 Use

DMA Transfers are initiated either through Software or Hardware Handshaking Interfaces. The Handshaking Interface is configurable on a per Channel basis. The following Hardware Handshaking Interfaces are available for selection:

Table 38. Hardware Handshake Interfaces

Transfer Type and Flow Control are configurable on a per Channel basis, the following Flow Control options are available depending on the Transfer Type:

Table 39. Transfer Type and Flow Control Options

Multi-Block Transfers are achieved through:

- Linked List (Block Chaining)
- Address Auto-Reloading
- Contiguous Addressing

There are 5 possible sources for Channel Interrupts, each of these sources can be individually masked. The sources are provided in the following list:

- 1. DMA Transfer Complete generated on DMA transfer completion to the Destination Peripheral.
- 2. Block Transfer Complete generated on DMA block transfer completion to the Destination Peripheral.
- 3. Source Transaction Complete generated after completion of the last AHB transfer of the requested single/burst transaction from the handshaking interface (either the hardware or software handshaking interface) on the source side.
- 4. Destination Transaction Complete generated after completion of the last AHB transfer of the requested single/burst transaction from the handshaking interface (either the hardware or software handshaking interface) on the destination side.
- 5. Error Response generated when an ERROR response is received from an AHB slave on the HRESP bus during a DMA transfer.

In the event on an ERROR response the DMA transfer is cancelled and the corresponding channel is disabled, an Error Response interrupt will be generated if the channel configured to do so.

16.3 Memory Mapped IO Registers

Registers listed are for the DMA Controller, starting at base address B0700000h.

16.3.1.1 Channel0 Source Address (SAR0)

Source Address of DMA transfer

The starting source address is programmed by software before the DMA channel is enabled, or by an LLI update before the start of the DMA transfer. While the DMA transfer is in progress, this register is updated to reflect the source address of the current transfer.

16.3.1.2 Channel0 Destination Address (DAR0)

Destination address of DMA transfer

The starting destination address is programmed by software before the DMA channel is enabled, or by an LLI update before the start of the DMA transfer. While the DMA transfer is in progress, this register is updated to reflect the destination address of the current transfer.

16.3.1.3 Channel0 Linked List Pointer (LLP0)

Program this register to point to the first Linked List Item (LLI) in memory prior to enabling the channel if block chaining is enabled

MEM Offset (00000000) 0B0700010h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Default** 0000_0000h

Size 32 bits

16.3.1.4 Channel0 Control LOWER (CTL_L0)

Contains fields that control the DMA transfer

It is part of the block descriptor (linked list item - LLI) when block chaining is enabled. It can be varied on a block-by-block basis within a DMA transfer when block chaining is enabled.

MEM Offset (00000000) 0B0700018h

Size 32 bits **Default** 0030_4801h

16.3.1.5 Channel0 Control UPPER (CTL_U0)

Contains fields that control the DMA transfer.

It can be varied on a block-by-block basis within a DMA transfer when block chaining is enabled. If status write-back is enabled, the content is written to the control register location of the LLI in system memory at the end of the block transfer.

16.3.1.6 Channel0 Source Status (SSTAT0)

This register is a temporary placeholder for the source status information on its way to the SSTAT0 register location of the LLI. The source status information should be retrieved by software from the SSTAT0 register location of the LLI, and not by a read of this register over the DMAC slave interface.

16.3.1.7 Channel0 Destination Status (DSTAT0)

This register is a temporary placeholder for the destination status information on its way to the DSTAT0 register location of the LLI. The destination status information should be retrieved by software from the DSTAT0 register location of the LLI and not by a read of this register over the DMAC slave interface

16.3.1.8 Channel0 Source Status Address (SSTATAR0)

After the completion of each block transfer, hardware can retrieve the source status information from the address pointed to by the contents of this register

16.3.1.9 Channel0 Destination Status Address (DSTATAR0)

After the completion of each block transfer, hardware can retrieve the destination status information from the address pointed to by the contents of this register

MEM Offset (00000000) 0B0700038h **Security_PolicyGroup IntelRsvd** False Factor Fa **Size** 32 bits

0000_0000h

16.3.1.10 Channel0 Configuration LOWER (CFG_L0)

Contains fields that configure the DMA transfer. The channel configuration register remains fixed for all blocks of a multi-block transfer. You need to program this register prior to enabling the channel.

MEM Offset (00000000) 0B0700040h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

16.3.1.11 Channel0 configuration UPPER (CFG_U0)

Contains fields that configure the DMA transfer. The channel configuration register remains fixed for all blocks of a multi-block transfer. You need to program this register prior to enabling the channel.

MEM Offset (00000000) 0B0700044h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor Fact **Size** 32 bits

16.3.1.12 Channel0 Source Gather (SGR0)

The CTL0_L.SINC field controls whether the address increments or decrements. For a fixed-address control, then the address remains constant throughout the transfer and this register is ignored.

16.3.1.13 Channel0 Destination Scatter (DSR0)

The CTL0_L.DINC field controls whether the address increments or decrements. For a fixed-address control, then the address remains constant throughout the transfer and this register is ignored.

16.3.1.14 Channel1 Source Address (SAR1)

Source Address of DMA transfer

The starting source address is programmed by software before the DMA channel is enabled, or by an LLI update before the start of the DMA transfer. While the DMA transfer is in progress, this register is updated to reflect the source address of the current transfer.

16.3.1.15 Channel1 Destination Address (DAR1)

Destination address of DMA transfer

The starting destination address is programmed by software before the DMA channel is enabled, or by an LLI update before the start of the DMA transfer. While the DMA transfer is in progress, this register is updated to reflect the destination address of the current transfer.

16.3.1.16 Channel1 Linked List Pointer (LLP1)

Program this register to point to the first Linked List Item (LLI) in memory prior to enabling the channel if block chaining is enabled

MEM Offset (00000000) 0B0700068h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor Factor False Factor Factor Factor Factor Factor Factor Factor Factor Factor Facto **Size** 32 bits

16.3.1.17 Channel1 Control LOWER (CTL_L1)

Contains fields that control the DMA transfer

It is part of the block descriptor (linked list item - LLI) when block chaining is enabled. It can be varied on a block-by-block basis within a DMA transfer when block chaining is enabled.

MEM Offset (00000000) 0B0700070h

Size 32 bits

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16.3.1.18 Channel1 Control UPPER (CTL_U1)

Contains fields that control the DMA transfer.

It can be varied on a block-by-block basis within a DMA transfer when block chaining is enabled. If status write-back is enabled, the content is written to the control register location of the LLI in system memory at the end of the block transfer.

16.3.1.19 Channel1 Source Status (SSTAT1)

This register is a temporary placeholder for the source status information on its way to the SSTAT0 register location of the LLI. The source status information should be retrieved by software from the SSTAT0 register location of the LLI, and not by a read of this register over the DMAC slave interface.

16.3.1.20 Channel1 Destination Status (DSTAT1)

This register is a temporary placeholder for the destination status information on its way to the DSTAT0 register location of the LLI. The destination status information should be retrieved by software from the DSTAT0 register location of the LLI and not by a read of this register over the DMAC slave interface

16.3.1.21 Channel1 Source Status Address (SSTATAR1)

After the completion of each block transfer, hardware can retrieve the source status information from the address pointed to by the contents of this register

16.3.1.22 Channel1 Destination Status Address (DSTATAR1)

After the completion of each block transfer, hardware can retrieve the destination status information from the address pointed to by the contents of this register

MEM Offset (00000000) 0B0700090h **Security_PolicyGroup IntelRsvd** False Factor Fa **Size** 32 bits

0000_0000h

16.3.1.23 Channel1 Configuration LOWER (CFG_L1)

Contains fields that configure the DMA transfer. The channel configuration register remains fixed for all blocks of a multi-block transfer. You need to program this register prior to enabling the channel.

MEM Offset (00000000) 0B0700098h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

16.3.1.24 Channel1 configuration UPPER (CFG_U1)

Contains fields that configure the DMA transfer. The channel configuration register remains fixed for all blocks of a multi-block transfer. You need to program this register prior to enabling the channel.

MEM Offset (00000000) 0B070009Ch **Security_PolicyGroup IntelRsvd** False
 Size 32 bit **Default** 0000_0004h

Size 32 bits

16.3.1.25 Channel1 Source Gather (SGR1)

The CTL0_L.SINC field controls whether the address increments or decrements. For a fixed-address control, then the address remains constant throughout the transfer and this register is ignored.

16.3.1.26 Channel1 Destination Scatter (DSR1)

The CTL0_L.DINC field controls whether the address increments or decrements. For a fixed-address control, then the address remains constant throughout the transfer and this register is ignored.

MEM Offset (00000000) 0B07000A8h **Security_PolicyGroup IntelRsvd** False False False 32 bit **Size** 32 bits

Default 0000_0000h

16.3.1.27 Raw Status for IntTfr Interrupt (RAW_TFR)

DMA Transfer Complete Interrupt. This interrupt is generated on DMA transfer completion to the destination peripheral

16.3.1.28 Raw Status for IntBlock Interrupt (RAW_BLOCK)

Block Transfer Complete Interrupt. This interrupt is generated on DMA block transfer completion to the destination peripheral.

16.3.1.29 Raw Status for IntSrcTran Interrupt (RAW_SRC_TRAN)

Source Transaction Complete Interrupt. Generated after completion of the last AHB transfer of the requested single/burst transaction from the handshaking interface (either the hardware or software handshaking interface) on the source side. NOTE: If the source is memory, then IntSrcTran interrupt should be ignored, as there is no concept of a DMA transaction level for memory

16.3.1.30 Raw Status for IntDstTran Interrupt (RAW_DST_TRAN)

Destination Transaction Complete Interrupt. Generated after completion of the last AHB transfer of the requested single/burst transaction from the handshaking interface (either the hardware or software handshaking interface) on the destination side. NOTE: If the destination for a channel is memory, then that channel will never generate the IntDstTran interrupt. Because of this, the corresponding bit in this field will not be set.

16.3.1.31 Raw Status for IntErr Interrupt (RAW_ERR)

Error Interrupt. This interrupt is generated when an ERROR response is received from an AHB slave on the HRESP bus during a DMA transfer. In addition, the DMA transfer is cancelled and the channel is disabled.

Peripheral controllers (SPI/I2C/UART) or memory controllers don?t generate error response. Only AHB Fabric can generate error response if address points to a hole. DMAC doesn't support slave AHB error response detection for Channel0 source and Channel1 destination transfers, which is acceptable limitation as only AHB fabric can generate error response and that too for address hole.

MEM Offset (00000000) 0B07002E0h **Security_PolicyGroup IntelRsvd** False Factor False Factor Factor False False Factor Facto **Default** 0000_0000h

Size 32 bits

16.3.1.32 Status for IntTfr Interrupt (STATUS_TFR)

DMA Transfer Complete Interrupt status

MEM Offset (00000000) 0B07002E8h **Security_PolicyGroup IntelRsvd** False False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

16.3.1.33 Status for IntBlock Interrupt (STATUS_BLOCK)

Block Transfer Complete Interrupt status

MEM Offset (00000000) 0B07002F0h **Security_PolicyGroup IntelRsvd** False Factor False **Default** 0000_0000h

Size 32 bits

16.3.1.34 Status for IntSrcTran Interrupt (STATUS_SRC_TRAN)

Source Transaction Complete Interrupt status

16.3.1.35 Status for IntDstTran Interrupt (STATUS_DST_TRAN)

Destination Transaction Complete Interrupt status

16.3.1.36 Status for IntErr Interrupt (STATUS_ERR)

Error Interrupt status

MEM Offset (00000000) 0B0700308h **Security_PolicyGroup IntelRsvd** False False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

16.3.1.37 Mask for IntTfr Interrupt (MASK_TFR)

DMA Transfer Complete Interrupt mask. The contents of the Raw Status register is masked with the contents of the Mask register.

16.3.1.38 Mask for IntBlock Interrupt (MASK_BLOCK)

Block Transfer Complete Interrupt mask. The contents of the Raw Status register is masked with the contents of the Mask register.

16.3.1.39 Mask for IntSrcTran Interrupt (MASK_SRC_TRAN)

Source Transaction Complete Interrupt mask. The contents of the Raw Status register is masked with the contents of the Mask register.

MEM Offset (00000000) 0B0700320h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Mask for IntDstTran Interrupt (MASK_DST_TRAN)

Destination Transaction Complete Interrupt mask. The contents of the Raw Status register is masked with the contents of the Mask register.

MEM Offset (00000000) 0B0700328h **Security_PolicyGroup IntelRsvd** False Factor False **Size** 32 bits

Default 0000_0000h

16.3.1.40 Mask for IntErr Interrupt (MASK_ERR)

Error Interrupt mask. The contents of the Raw Status register is masked with the contents of the Mask register.

MEM Offset (00000000) 0B0700330h **Security_PolicyGroup IntelRsvd** False Factor Factor Factor Factor Factor False Factor Fac **Size** 32 bits

16.3.1.41 Clear for IntTfr Interrupt (CLEAR_TFR)

DMA Transfer Complete Interrupt clear

MEM Offset (00000000) 0B0700338h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

16.3.1.42 Clear for IntBlock Interrupt (CLEAR_BLOCK)

Block Transfer Complete Interrupt clear

MEM Offset (00000000) 0B0700340h **Security_PolicyGroup IntelRsvd** False False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

16.3.1.43 Clear for IntSrcTran Interrupt (CLEAR_SRC_TRAN)

Source Transaction Complete Interrupt clear

MEM Offset (00000000) 0B0700348h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits
 Default 0000 0

16.3.1.44 Clear for IntDstTran Interrupt (CLEAR_DST_TRAN)

Destination Transaction Complete Interrupt clear

MEM Offset (00000000) 0B0700350h **Security_PolicyGroup IntelRsvd** False False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

16.3.1.45 Clear for IntErr Interrupt (CLEAR_ERR)

Error Interrupt clear

MEM Offset (00000000) 0B0700358h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits
 Default 0000 0

16.3.1.46 Combined Interrupt Status (STATUS_INT)

The contents of each of the Status registers is ORed to produce a single bit for each interrupt type in this Combined Interrupt Status register.

MEM Offset (00000000) 0B0700360h

Size 32 bits **Default** 0000_0000h

16.3.1.47 Source Software Transaction Request (REQ_SRC_REG)

MEM Offset (00000000) 0B0700368h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

0000_0000h

16.3.1.48 Destination Software Transaction Request register (REQ_DST_REG)

MEM Offset (00000000) 0B0700370h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

16.3.1.49 Source Single Transaction Request (SGL_REQ_SRC_REG)

MEM Offset (00000000) 0B0700378h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits **Default** 0000_0000h

16.3.1.50 Destination Single Software Transaction Request (SGL_REQ_DST_REG)

MEM Offset (00000000) 0B0700380h **Security_PolicyGroup IntelRsvd** False False False 32 bit **Size** 32 bits

16.3.1.51 Source Last Transaction Request (LST_SRC_REG)

MEM Offset (00000000) 0B0700388h **Security_PolicyGroup IntelRsvd** False False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

16.3.1.52 Destination Single Transaction Request (LST_DST_REG)

MEM Offset (00000000) 0B0700390h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

16.3.1.53 DMA Configuration (DMA_CFG_REG)

Used to enable the DMA controller (DMAC), which must be done before any channel activity can begin.

If the global channel enable bit is cleared while any channel is still active, then DMA_EN still returns 1 to indicate that there are channels still active until hardware has terminated all activity on all channels, at which point the DMA_EN bit returns 0

16.3.1.54 Channel Enable (CH_EN_REG)

Software can read this register in order to find out which channels are currently inactive if needs to set up a new channel. It can then enable an inactive channel with the required priority.

DMA Controller

16.3.1.55 DMA ID (DMA_ID_REG)

Reads back the coreConsultant configured hardcoded ID number

16.3.1.56 DMA Test (DMA_TEST_REG)

This register is used to put the AHB slave interface into test mode, during which the readback value of the writable registers match the value written. In normal operation, the readback value of some registers is a function of the DMA state and does not match the value written.

MEM Offset (00000000) 0B07003B0h

Size 32 bits

16.3.1.57 DMA Component ID - LOWER (DMA_COMP_ID_L)

Read-only register that specifies the version of the packaged component

MEM Offset (00000000) 0B07003F8h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits **Default** 4457_1110h

16.3.1.58 DMA Component ID - UPPER (DMA_COMP_ID_U)

Read-only register that specifies the component type

MEM Offset (00000000) 0B07003FCh **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

Default 3231_382Ah

General Purpose I/O (GPIO)

The SoC contains a single instance of the GPIO controller. The GPIO controller provides a total of 25 GPIOs.

17.1 Signal Descriptions

Please see Chapter [2,](#page-20-0) ["Physical Interfaces"](#page-20-0) for additional details.

The signal description table has the following headings:

- **Signal Name:** The name of the signal/pin
- **Direction:** The buffer direction can be either input, output, or I/O (bidirectional)
- **Type:** The buffer type found in Chapter [4,](#page-39-0) ["Electrical Characteristics"](#page-39-0)
- **Description:** A brief explanation of the signal's function

Table 40. [Memory S](#page-105-0)ignals

NOTE: Signal Names are preliminary and are subject to changes when the "Physical Interfaces" Chapter is populated.

17.2 Features

The following is a list of the GPIO controller features:

- 25 independently configurable GPIOs
- Separate data register bit and data direction control bit for each GPIO
- Metastability registers for GPIO read data
- Interrupt mode supported for all GPIOs, configurable as follows:
	- o Active High Level
o Active Low Level
	- **Active Low Level**
	- o Rising Edge
	- o Falling Edge
	- o Both Edge
- Debounce logic for interrupt sources

17.3 Memory Mapped IO Registers

Registers listed are for GPIO, starting at base address B0000C00h.

Table 41. Summary of GPIO Registers—0xB0000C00

17.3.1.1 Port A Data (GPIO_SWPORTA_DR)

Contains the GPIO Port data bits

MEM Offset (B0000C00) 0B0000C00h **Security_PolicyGroup** IntelRsvd False **Size** 32 bits **Default** 0000_0000h

17.3.1.2 Port A Data Direction (GPIO_SWPORTA_DDR)

Used to control the GPIO Port bits data direction

MEM Offset (B0000C00) 0B0000C04h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

17.3.1.3 Port A Data Source (GPIO_SWPORTA_CTL)

Used to control the GPIO Port Data Source

MEM Offset (B0000C00) 0B0000C08h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

Default 0000_0000h

17.3.1.4 Interrupt Enable (GPIO_INTEN)

Used to configured Port A bits as interrupt sources

17.3.1.5 Interrupt Mask (GPIO_INTMASK)

Controls masking for Port A bits configured as interrupt sources

MEM Offset (B0000C00) 0B0000C34h **Security_PolicyGroup IntelRsvd** False
 Size 32 bit **Size** 32 bits

17.3.1.6 Interrupt Type (GPIO_INTTYPE_LEVEL)

Controls the type of interrupt associated with Port A bits configured as interrupt source

MEM Offset (B0000C00) 0B0000C38h **Security_PolicyGroup IntelRsvd** False Factor False Factor Factor False False Factor Facto **Size** 32 bits

17.3.1.7 Interrupt Polarity (GPIO_INT_POLARITY)

Controls the interrupt polarity associated with Port A bits configured as interrupt sources

17.3.1.8 Interrupt Status (GPIO_INTSTATUS)

Stores the interrupt status after masking for Port A bits configured as interrupt sources

MEM Offset (B0000C00) 0B0000C40h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits **Default** 0000_0000h

17.3.1.9 Raw Interrupt Status (GPIO_RAW_INTSTATUS)

MEM Offset (B0000C00) 0B0000C44h **Security_PolicyGroup IntelRsvd** False False False 51 **Default** 0000_0000h

Size 32 bits

17.3.1.10 Debounce Enable (GPIO_DEBOUNCE)

Controls the debounce logic associated to a Port A bit configured as interrupt source

17.3.1.11 Clear Interrupt (GPIO_PORTA_EOI)

Controls edge-type interrupt clearing

17.3.1.12 Port A External Port (GPIO_EXT_PORTA)

Used by the software to read values from the GPIO Port bits

MEM Offset (B0000C00) 0B0000C50h **Security_PolicyGroup IntelRsvd** False False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

17.3.1.13 Synchronization Level (GPIO_LS_SYNC)

Controls if a level-sensitive interrupt type need to be synchronized to the system clock

MEM Offset (B0000C00) 0B0000C60h **Security_PolicyGroup IntelRsvd** False Factor False **Default** 0000_0000h

Size 32 bits

17.3.1.14 Interrupt both edge type (GPIO_INT_BOTHEDGE)

Controls the edge type of interrupt that can occur on Port A

MEM Offset (B0000C00) 0B0000C68h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

17.3.1.15 GPIO Configuration Register 2 (GPIO_CONFIG_REG2)

Stores the bit Port width minus one

17.3.1.16 GPIO Configuration Register 1 (GPIO_CONFIG_REG1)

Stores information on the GPIO controller configuration

The Timer and Pulse Width Modulation (PWM) block allows individual control of the frequency and duty cycle of two output signals. The PWM block also supports use as a Timer block for the purposes of generating periodic interrupts.

18.1 Signal Descriptions

Please see Chapter [2,](#page-20-0) ["Physical Interfaces"](#page-20-0) for additional details.

The signal description table has the following headings:

- **Signal Name:** The name of the signal/pin
- **Direction:** The buffer direction can be either input, output, or I/O (bidirectional)
- **Type:** The buffer type found in Chapter [4,](#page-39-0) ["Electrical Characteristics"](#page-39-0)
- **Description:** A brief explanation of the signal's function

Table 42. External Interface Signals

NOTE: Signal Names are preliminary and are subject to changes when the "Physical Interfaces" Chapter is populated.

18.2 Features

The following is a list of the PWM features:

- 2 Counters capable of operating in PWM Mode or Timer Mode
- PWM Mode
	- o Configurable High and Low times for each PWM Output
		- Minimum High and Low time of 2 32MHz clock periods
		- (8MHz)
			- Maximum High and Low time of 2^32 32MHz clock periods
		- $(< 1Hz)$
	- o High and Low time granularity of a single 32MHz clock period
	- o Interrupt generation always on both the rising and falling edges of the PWM Output
	- o Interrupt Control per PWM Output:
		- Interrupt Generation only on both edges of the PWM **Output**

- Interrupt Mask Capability
- Timer Mode
	- o 32-bit Timer operating at 32MHz
		- Timer Periods from 1 32MHz clock period (31.25ns)
		- to 2^32-1 32MHz clock periods (134s)
	- o Interrupt Control per Timer:
		- Interrupt Generation on Timer Expiry
		- **Interrupt Mask Capability**

18.2.1 PMW Signaling

The Timer and PWM block supports the generation of PWM Output signals with configurable low and high times which allows both the duty cycle and frequency to be set.

Some example PWM Output signals are shown in the following figures.

Figure 12. Duty Cycle of 20%

Figure 13. Duty Cycle of 50%

Figure 14. Duty Cycle of 80%

See Section [18.3.1](#page-349-0) for details on configuring the low and high times.

18.2.2 Functional Operation

Each counter is identical, has an associated PWM Output and can be individually configured with the following options:

- Enable
- PWM Mode or Timer Mode
- PWM Duty Cycle and Frequency
- Timer Timeout Period
- Interrupt Masking

In PMW Mode the high and low times can be configured as follows. This assumes a nominal system clock frequency of 32MHz, the values, in nanoseconds, will differ if the system clock frequency is changed.

Table 43. PWM Timing

See Section [18.3.1](#page-349-0) for details on configuring the low and high times.

PWM Mode supports the following maskable interrupt source:

• Both edges of the PWM Output signal.

In Timer Mode the timeout period can be configured as follows. This assumes a nominal system clock frequency of 32MHz, the values, in nanoseconds, will differ if the system clock frequency is changed.

Table 44. Timer Period

See Section [18.3.2](#page-350-0) for details on configuring the timeout period.

Timer Mode supports the following maskable interrupt source:

• Timer Expiry.

Interrupts are cleared by reading the Timer N End Of Interrupt register.

18.3 Use

18.3.1 PWM Mode

Once enabled, the counter runs in free running mode and the associated PWM Output is set to 0.

The Low Time is determined by the Timer N Load Count register value which is loaded into counter upon enable, once the counter decrements to 0 the associated PWM Output toggles from 0 to 1 and the counter is loaded with the Timer N Load Count 2 register value which determines the High time.

When the counter subsequently decrements to 0 the associated PWM Output toggles from 1 to 0 and the timer is re-loaded with the Timer N Load Count register value and the process repeats.

18.3.2 Timer Mode

When a timer counter is enabled after being reset or disabled, the count value is loaded from the TimerNLoadCount register; this occurs in both free-running and userdefined count modes.

When a timer counts down to 0, it loads one of two values, depending on the timer operating mode:

- User-defined count mode Timer loads the current value of TimerNLoadCount or TimerNLoadCount2 register alternatingly. One can program same value into TimerNLoadCount and TimerNLoadCount2 registers for same interrupt periodicity. Use this mode if a fixed periodic timed interrupt is needed.
- Free-running mode Timer loads the maximum value of 32-bits of all-ones. The timer counter wrapping to its maximum value allows time to reprogram or disable the timer before another interrupt occurs. Use this mode if a single timed interrupt is needed. After getting the interrupt, disable the timer so that it is stopped before it fires another interrupt after 2^{32} timer clock ticks.

In both the timer operating modes, timer counter is always running/decrementing at every timer clock tick, unless timer is disabled. An interrupt is generated when the timer count changes from 0 to its maximum count value.

In Timer Mode the PWM Outputs are unused and associated pins can be freed up for alternative functions by reconfiguring the pin muxing.

18.4 Memory Mapped IO Registers

Registers listed are for Timers, starting at base address B0000800h.

Table 45. Summary of PWM Registers—0xB0000800

18.4.1.1 Timer 1 Load Count (Timer1LoadCount)

18.4.1.2 Timer 1 Current Value (Timer1CurrentValue)

MEM Offset (B0000800) 0B0000804h **Security_PolicyGroup IntelRsvd** False False

Size 32 bit **Default** 0000_0000h

Size 32 bits

18.4.1.3 Timer 1 Control (Timer1ControlReg)

MEM Offset (B0000800) 0B0000808h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

18.4.1.4 Timer 1 End Of Interrupt (Timer1EOI)

MEM Offset (B0000800) 0B000080Ch **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

Default 0000_0000h

18.4.1.5 Timer 1 Interrupt Status (Timer1IntStatus)

MEM Offset (B0000800) 0B0000810h **Security_PolicyGroup IntelRsvd** False False False 32 bit **Size** 32 bits

18.4.1.6 Timer 2 Load Count (Timer2LoadCount)

MEM Offset (B0000800) 0B0000814h

Size 32 bits **Default** 0000_0000h

18.4.1.7 Timer 2 Current Value (Timer2CurrentValue)

MEM Offset (B0000800) 0B0000818h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor Factor False Factor Factor Factor Factor Factor Factor Factor Factor Factor Facto **Size** 32 bits

18.4.1.8 Timer 2 Control (Timer2ControlReg)

MEM Offset (B0000800) 0B000081Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0000h

18.4.1.9 Timer 2 End Of Interrupt (Timer2EOI)

MEM Offset (B0000800) 0B0000820h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

18.4.1.10 Timer 2 Interrupt Status (Timer2IntStatus)

MEM Offset (B0000800) 0B0000824h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

18.4.1.11 Timers Interrupt Status (TimersIntStatus)

MEM Offset (B0000800) 0B00008A0h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor False Factor Facto **Size** 32 bits

Default 0000_0000h

18.4.1.12 Timers End Of Interrupt (TimersEOI)

MEM Offset (B0000800) 0B00008A4h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits **Default** 0000_0000h

18.4.1.13 Timers Raw (unmasked) Interrupt Status (TimersRawIntStatus)

MEM Offset (B0000800) 0B00008A8h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

0000_0000h

18.4.1.14 Timers Component Version (TimersCompVersion)

18.4.1.15 Timer 1 Load Count 2 (Timer1LoadCount2)

MEM Offset (B0000800) 0B00008B0h

Size 32 bits **Default** 0000_0000h

18.4.1.16 Timer 2 Load Count 2 (Timer2LoadCount2)

MEM Offset (B0000800) 0B00008B4h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor Fact **Size** 32 bits

Default 0000_0000h

The Watchdog Timer can be used to trigger a Warm Reset in the event that the SoC has become unresponsive.

19.1 Features

The following is a list of the Watchdog (WDT) features:

- Timer can be disabled (default state) or locked enabled (SoC Warm Reset required to disable)
- Selectable Timeout Value that ranges from 8us to ~60s (32MHz)
- Capability to have a different initial Timeout Value versus the reload Timeout Value
- 2 Timeout Response Modes as Follows:
	- o Request a SoC Warm Reset when a timeout occurs.
	- o Generate an Interrupt when a timeout occurs and if the Interrupt is not serviced by the time a second timeout occurs then requests a SoC Warm Reset.

19.1.1 WDT Enable

The WDT_CR.WDT_EN register field must be set to 1 to enable the WDT, once set to 1 the WDT EN field can only be set back to 0 by an SoC Reset.

19.1.2 WDT Timeout Capabilities

The timer uses a 32-bit down-counter which is loaded with the programmed Timeout Value.

The Initial Timeout Value is selected by the WDT_TORR.TOP_INIT register field (which is fixed to 0), this value gets loaded into the timer when the WDT is first enabled. The Reload Timeout Value is selected by the WDT_TORR.TOP register field, this value gets loaded into the timer on subsequent reloads of the timer.

The values below are based off a 32 MHz System Clock and must be adjusted if the frequency is adjusted (see Clocking Section).

Table 46. WDT Timeout Selection

Watchdog Timer

19.2 Use

When enabled the timer starts counting down from the programmed Timeout Value. If the processor fails to reload the counter before it reaches zero (timeout) the WDT will do one of two things depending on the programmed Response Mode:

Table 47. WDT Response Mode

•

NOTE: When the counter reaches zero it will wrap to the programmed Timeout Value and continue decrementing.

Figure 15. WDT Behaviour for Response Mode of 1

The counter is reloaded by writing 76h to the Counter Restart Register, this will also clear the WDT Interrupt.

The WDT Interrupt may also be cleared by reading the Interrupt Clear Register, however this will not reload the counter.

19.3 Memory Mapped IO Registers

Registers listed are for the WDT, starting at base address B0000000h

Watchdog Timer

Table 48. Summary of WDT Registers—0xB0000000

19.3.1.1 Control Register (WDT_CR)

Size 32 bits **Default** 0000_0002h

19.3.1.2 Timeout Range Register (WDT_TORR)

19.3.1.3 Current Counter Value Register (WDT_CCVR)

19.3.1.4 Current Restart Register (WDT_CRR)

19.3.1.5 Interrupt Status Register (WDT_STAT)

19.3.1.6 Interrupt Clear Register (WDT_EOI)

19.3.1.7 Component Parameters (WDT_COMP_PARAM_5)

19.3.1.8 Component Parameters (WDT_COMP_PARAM_4)

19.3.1.9 Component Parameters (WDT_COMP_PARAM_3)

19.3.1.10 Component Parameters (WDT_COMP_PARAM_2)

19.3.1.11 Component Parameters Register 1 (WDT_COMP_PARAM_1)

19.3.1.12 Component Version Register (WDT_COMP_VERSION)

19.3.1.13 Component Type Register (WDT_COMP_TYPE)

The SoC contains a Real Time Clock for the purpose of keeping track of time. The RTC operates from 1 Hz to 32.768 kHz.

The RTC supports alarm functionality that allows scheduling an Interrupt / Wake Event for a future time.

The RTC operates in all SoC Power States. The RTC is powered from the same battery supply as the rest of the SOC and does not have its own dedicated supply.

20.1 Signal Descriptions

Please see Chapter [2,](#page-20-0) ["Physical Interfaces"](#page-20-0) for additional details.

The signal description table has the following headings:

- **Signal Name:** The name of the signal/pin
- **Direction:** The buffer direction can be either input, output, or I/O (bidirectional)
- **Type:** The buffer type found in Chapter [4,](#page-39-0) ["Electrical Characteristics"](#page-39-0)
- Description: A brief explanation of the signal's function

Table 49. [Memory](#page-105-0) Signals

NOTE: Signal Names are preliminary and are subject to changes when the "Physical Interfaces" Chapter is populated.

20.2 Features

The following is a list of the RTC features:

- Programmable 32 bit binary Counter
- Counter increments on successive edges of a Counter Clock from 1 Hz to 32.768 kHz (derived from the 32.768 kHz Crystal Oscillator clock)
- Comparator for Interrupt / Wake Event generation based on the programmed Match Value
- Supports Interrupt / Wake Event generation when only the Counter Clock is running (Fabric Clock is off)

20.2.1 RTC Clock

The RTC clock is the output of a 4bit prescaler (see Clocking Section) that is driven by the output of the 32.768 kHz Crystal Oscillator.

This allows a range of clock frequencies to be generated as shown in the table below:

Table 50. RTC Clock Scaling

20.2.2 Counter Functionality

The RTC contains a single 32bit up-counter, the counter starts to increment when the RTC is taken out of reset. The counter increments on successive edges of the RTC clock.

The counter Start Value is loaded by writing a 32bit value to the Counter Load Register. The Counter supports loading a Start Value while it is incrementing.

When the counter reaches its max value $(2^{32}-1)$ it wraps to 0 and continues incrementing.

The RTC supports reading the Counter via the read-only Counter Value Register.

For accessing any registers in RTC block, both APN Clock (pclk) and counter clock (rtcclk) should be running and the frequency of the APB Bus clock must be greater than three times the frequency of the counter clock. If CCU_SYS_CLK_SEL register in SCSS is configured to choose rtcclk for system clock, then CCU_RTC_CLK_DIB register in SCSS shall be configured for div-by-4 or lower, in order to ensure that all register accesses to RTC block are properly synchronized to counter clock (rtcclk) domain.

After writing a register, firmware has to wait for atleast 1 rtcclk input before clock gating pclk. Interrupt status bit (rtc_stat) in RTC_STAT/RTC_RSTAT register will get cleared 1 rtcclk period after reading RTC_EOI register. Alternatively firmware can choose to ignore the interrupt status register and rely only on the rtc_intr line interrupt for interrupt status, which gets cleared immediately after reading RTC_EOI register.

20.3 Use

The RTC allows the user to disable interrupt generation and also to mask a generated interrupt.

For accessing any registers in RTC block, both APN Clock (pclk) and counter clock (rtcclk) should be running and the frequency of the APB Bus clock must be greater than three times the frequency of the counter clock. If CCU_SYS_CLK_SEL register in SCSS is configured to choose rtcclk for system clock, then CCU_RTC_CLK_DIB register in SCSS shall be configured for div-by-4 or lower, in order to ensure that all register accesses to RTC block are properly synchronized to counter clock (rtcclk) domain.

After writing a register, firmware has to wait for atleast 1 rtcclk input before clock gating pclk. Interrupt status bit (rtc_stat) in RTC_STAT/RTC_RSTAT register will get cleared 1 rtcclk period after reading RTC_EOI register. Alternatively firmware can choose to ignore the interrupt status register and rely only on the rtc_intr line interrupt for interrupt status, which gets cleared immediately after reading RTC_EOI register.

20.3.1 Clock and Calendar

The 32bit counter is intended to provide Clock and Calendar functionality, the capabilities differ depending on the chosen frequency of the RTC clock as described in the examples below.

Using a 1 Hz RTC clock the following capabilities are exposed:

- Counter increments every second
- Counter wraps in 2^{32} -1 seconds (~136 years)
- Counter can be used to store Time and Date in the Unix Time format defined as the number of seconds since 00:00:00 UTC on 1 January 1970 (the epoch)

Using a 32.68 kHz RTC clock the following capabilities are exposed:

- Counter increments every 30.5 microsecond
	- Counter wraps in 2^{32} -1 $*$ 30.5 microsecond (~1.51 days)

20.3.2 Alarm

Alarm functionality is provided by the Match Value Register, the interrupt generation logic asserts the interrupt (if enabled) when the Counter reaches this Match Value.

The RTC allows the user to disable interrupt generation and also to mask a generated interrupt.

Additionally the RTC supports generation of an interrupt when only the RTC clock is running, this allows the interrupt to be generated when in the Deep Sleep state.

20.3.3 Wake Event

The RTC supports waking the SoC from Low Power States, including Sleep.

The SoC use the RTC interrupt as the source of this wake event so interrupt generation must be enabled to facilitate this RTC wake capability.

20.4 Memory Mapped IO Registers

Registers listed are for RTC, starting at base address B000400h.

Table 51. Summary of RTC Registers—0xB0000400

20.4.1.1 Current Counter Value Register (RTC_CCVR)

MEM Offset (B0000400) 0h **Security_PolicyGroup IntelRsvd** False Factor False Factor False Factor Fact **Size** 32 bits

Default 0000_0000h

20.4.1.2 Current Match Register (RTC_CMR)

Default 0000_0000h

20.4.1.3 Counter Load Register (RTC_CLR)

20.4.1.4 Counter Control Register (RTC_CCR)

20.4.1.5 Interrupt Status Register (RTC_STAT)

20.4.1.6 Interrupt Raw Status Register (RTC_RSTAT)

Default 0000_0000h

20.4.1.7 End of Interrupt Register (RTC_EOI)

20.4.1.8 End of Interrupt Register (RTC_COMP_VERSION)

The SOC supports 19 Low power comparators which can be used to wake the system from low power states. Two types of comparators are supported, a Low power, low performance version and a high power high performance version. Analog Inputs [5:0] are connected to high performance comparators and Analog Inputs [18:6] are connected to low power comparators.

Each comparator can be powered down to achieve even lower power. Comparator reference supply is selectable between the internal VREF (0.95V +/- 10%) and an external user supplied reference (AR input).

21.1 Signal Descriptions

Table 52. [Memory](#page-105-0) Signals

21.2 Features

The following is a list of comparator features:

- 2.0V 3.63V AVDD operation
- 1.2V 1.98V DVDD operation
- Fast Asynchronous comparator
- 1 Positive and 2 negative inputs with selectable digital input
- Rail to rail input range
- CMPLP
	- o <3.8us propagation delay
	- o <600nA static current
	- o <10mV hysteresis (6 mV typ)
	- o <22nA power down current
- CMPHP
	- o <0.25us propagation delay
	- o <9.8uA static current
	- o <6.8mV hysteresis (4.6 mV typ)
	- o <2.7nA power down current

21.3 Use

The 19 comparators can be used in the following ways

- 1) To generate an interrupt to the processor
- 2) To generate a wake event to cause the PMU to exit a deep sleep condition.

The following sequence should be applied setting up the comparator control to generate an interrupt or wake event.

- 1) Set CMP_REF_SEL for each comparator
- 2) Set CMP_REF_POL for each comparator
- 3) Set CMP_PWR for each comparator to '1'
- 4) Set CMP_EN for each comparator to '1'

The comparator interrupt is a level triggered interrupt based on the polarity set in CMP_REF_POL. It is not edge triggered. Interrupt is latched when external analog input matches that of CMP_REF_POL and this latch is cleared using CMP_STAT_CLR. Interrupt persists as long as the external source maintains its signal state as that of CMP_REF_POL , and the particular comparator is enabled $(CMP_EN[x]=1)$.

The following sequence should be used when responding to an interrupt having being asserted.

1) Read CMP_STAT_CLR for each comparator

2) Clear CMP_STAT_CLR for each firing comparator by writing a '1'

If the external analog input generates a pulse matching polarity level of CMP_REF_POL for sufficient duration greater than comparator's propagation delay, interrupt gets latched. If external input maintains its signal state to that of CMP_REF_POL, interrupt persists and is not cleared even if CMP_STAT_CLR is applied.

The comparators are directly connected to the PMU logic in the always on domain of the SOC. When a comparator activates the PMU will exit its low power wait or deep sleep states. (See [Power management](#page-60-0) for more details)

§

22 Analog to Digital Convertor (ADC)

The SoC implements a Successive-Approximation (SAR) Analog to Digital Convertor (ADC) which is capable of taking 19 single-ended analog inputs for conversion. ADC is characterized to operate over the AVDD (1.8 to 3.6 V) analog input range.

22.1 Signal Descriptions

Please see Chapter [2,](#page-20-0) ["Physical Interfaces"](#page-20-0) for additional details.

The signal description table has the following headings:

- **Signal Name:** The name of the signal/pin
 Direction: The buffer direction can be eith
- **Direction:** The buffer direction can be either input, output, or I/O (bidirectional)
- **Type:** The buffer type found in Chapter [4,](#page-39-0) ["Electrical Characteristics"](#page-39-0)
- Description: A brief explanation of the signal's function

Table 53. [Memory](#page-105-0) Signals

22.2 Features

The following is a list of the ADC features:

- 19:1 multiplexed single-ended analog input channels, 6 high speed inputs and 13 low speed inputs.
- Selectable Resolution between 12, 10, 8 and 6-bit (12-bit at 2.28 MSps and 6 bits at 4 MSps).
	- o Max achievable sampling rate = (adc clock frequency) / (selres $+ 2$).
- ADC Parameters:
	- o Differential Non-Linearity DNL = $+/$ 1.0 LSB
	- o Integral Non-Linearity $INL = +/- 2.0$ LSB
	- \circ SINAD = 68 dBFS
	- o Offset Error = $+/- 2$ LSB (calibration enabled), $+/- 64$ LSB (calibration disabled)
- Latencies:
	- o Power-up time of \leq = 10 us
	- o 1 Conversion cycle = (resolution bits $+ 2$) cycles
- Full-scale input range is 0 to AVDD.
	- o ADC Reference Voltage (Vrefp) of ADC HIP is connected to AVDD.

- Current Consumption:
	- o ~18 uA at 10 kSPS
	- \circ ~240 uA at 1 MSPS
 \circ ~1 1 mA at 5 MSPS
	- o \sim 1.1 mA at 5 MSPS
o \sim 15 uA standby
	- \sim 15 uA standby
	- o ~2 uA powerdown

Notes:

- 1. ADC Hard macro takes in adcclk in the range of 140 kHz to 32 MHz. Minimum clock frequency is 140 kHz. adcclk is derived from system clock by configuring CCU_PERIPH_CLK_DIV_CTL0.CCU_ADC_CLK_DIV register in SCSS.
- 2. ADC Hard macro at its max sampling rate takes selres resolution + 2 cycles. For 12-bit resolution, it takes 14 cycles to get a sample. To read the sample by processor/DMA, it takes 3 system clock cycles minimum. Depending on number of cycles spent by processor for interrupt servicing and to process a given set of samples, max achievable sampling rate at system level could be lesser than or equal to max possible sampling rate (12-bit at 2.28 MSps, 10 bit at 2.6 MSps, 8-bit at 3.2 MSps and 6 bits at 4 MSps).
- 3. Minimum sampling rate is a function of adclk's min frequency of 140 kHz = 140 kHz / (selres + 2). Additionally there is a sampling window SW[7:0] register to delay sampling. For any sampling rate below this limit, software has to time and then trigger conversion accordingly.

22.3 Use

After powerup/cold reset, ADC is in deep power down state. Depending on current consumption and entry/exit latencies involved, firmware can put the ADC in different power states. When ADC is not in use, it is better to put it in low power states to reduce current consumption.

Whenever exit from deep power down mode or at power up/cold reset, Calibration has to be performed to reduce offset error from $+/-64$ LSB to $+/-2$ LSB.

At Power-up / cold reset cycle / transitioning from any other power modes (Deep Power Down or Power Down or Standby) to normal mode (with calibration or without calibration), below steps are to be performed:

- 1. Issue "Normal with/without calibration" command through ADC_OP_MODE register (OM="Normal with calibration" or "Normal Without Calibration", Delay $=$ 500). Note that Calibration is required if offset error $(+/- 64$ LSB) has to be reduced to $+/- 2$ LSB.
- 2. Issue "Start Calibration" command by writing ADC_command = Start calibration in ADC Command Register. This step is optional if calibration is not required. Optionally "Load Calibration" command can be performed if previous calibration word is restored. (AND/OR)

Issue a dummy conversion cycle. Dummy conversion cycle is not required if "Start calibration" is performed. This is done by:

- a. Setting ADC channel sequence table with one entry (channel $= 0$).
- b. Issue ADC Command, with sampling window SW=0, Number of samples $NS = 0$ (1 sample), ADC command = Start Single Shot Conversion.
- 3. Use ADC as required.
- 4. Later on, depending on whether ADC is in use or not, power state can be lowered to standby/powerdown depending on required power saving and acceptable entry/exit latency. Before the soc/system is put into "Deep sleep" power state, ADC has to be put to "Deep Power Down" state.

For converting analog input to digital sample once ADC is in normal/ON power state with calibration completed, the programming sequence for doing either single shot conversion or continuous conversion is:

- 1. Setup ADC Interrupt Enable register.
- 2. Setup ADC Channel Sequence table based on channel inputs to be converted.
- 3. Issue ADC Command, with setting sampling window, resolution, ADC_command = Start Single Conversion or Start Continuous Conversion. Number of Samples is used to stop single conversion once configured total number of samples (NS+1) are collected from channels as per channel sequence table. In case of continuous conversion, interrupt is raised every Ns number of samples are collected.

A continuous conversion can later be stopped by issuing ADC command with ADC command = Stop Continuous conversion.

22.4 Memory Mapped IO Registers

Registers listed are for ADC, starting at base address B0004000h.

Table 54. Summary of ADC Registers—0xB0004000

22.4.1.1 ADC Channel Sequence Table (ADC_SEQ [0..7])

Security_PolicyGroup IntelRsvd False **Default** 8080_8080h

MEM Offset (00000000) [0]:0h [1]:4h [2]:8h [3]:0Ch [4]:10h [5]:14h [6]:18h [7]:1Ch

Size 32 bits

22.4.1.2 ADC Command Register (ADC_CMD)

This register returns 0x0 value when ADC Calibration & Conversion is in IDLE state waiting for a new command. When a command is written and is not completed yet (state machine not in IDLE state), then reading back this register returns value written as part of issuance of command.

22.4.1.3 ADC Interrupt Status Register (ADC_INTR_STATUS)

22.4.1.4 ADC Interrupt Enable (ADC_INTR_ENABLE)

22.4.1.5 ADC Sample Register (ADC_SAMPLE)

22.4.1.6 ADC Calibraton Data Register (ADC_CALIBRATION)

22.4.1.7 ADC FIFO Count Register (ADC_FIFO_COUNT)

MEM Offset (00000000) 34h **Security_PolicyGroup IntelRsvd** False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

22.4.1.8 ADC Operating Mode Register (ADC_OP_MODE)

MEM Offset (00000000) 38h **Security_PolicyGroup IntelRsvd** False Factor False **Size** 32 bits

Default 0000_0FA0h

23 Interrupt Routing

The Interrupt Routing consists of several elements:

- 1. Internal Host Processor Interrupts
- 2. SoC Interrupts with configurable routing to Processor
- 3. Capability for SoC Interrupts to trigger a Processor Halt for Debug
- 4. Capability for SoC Interrupts to trigger a Warm Reset

23.1 Interrupt Routing

23.1.1 Host Processor Interrupts

The Interrupt Vector Assignments for the Host Processor are described in [Table](#page-394-0) 53:

Table 55. Host Processor Interrupt Vector Assignments

Interrupt Vectors 0 to 31 are due to events internal to the Host Processor, interrupts due to SoC events are routed through the User Defined Interrupts.

The User Defined Interrupts are delivered to the Host Processor via the PIC which maps particular Interrupt Inputs (IRQs) to configured Interrupt Vectors before presenting the interrupt to the Processor. The SoC Interrupt table shows the IRQ number into the PIC rather than the hardwired Interrupt Vector.

23.1.2 SoC Interrupts and Routing

Unused IRQs (63-51) in [Table](#page-395-0) 54 are Reserved. Interrupts have fixed high priority. Higher the IRQ number, higher is its priority.

Table 56. SoC Interrupt List and Routing Capability
Interrupt Routing

The System Control Subsystem (SCSS) contains functional blocks that control power sequencing, clock generation, reset generation, interrupt routing and pin muxing.

24.1 Features

The following is a list of the System Control Subsystem (SCSS) features:

- Clock Generation and Control
- Reset Generation
- Interrupt Routing
- Pin Mux Control
- SoC Configuration Registers
- Always-On Counter
- Always-On Periodic Timer

24.2 Memory Mapped IO Registers

Registers listed are for the SCSS, starting at base address B0800000h.

Table 57. Summary of SCSS Registers—0xB0800000

24.3 Register Detailed Description

24.3.1.1 Hybrid Oscillator Configuration 0 (OSC0_CFG0)

MEM Offset (00000000) 0h **Security_PolicyGroup IntelRsvd** False Factor False **Size** 32 bits

24.3.1.2 Hybrid Oscillator status 1 (OSC0_STAT1)

24.3.1.3 Hybrid Oscillator configuration 1 (OSC0_CFG1)

Size 32 bits **Default** 0000_0302h

24.3.1.4 RTC Oscillator status 0 (OSC1_STAT0)

MEM Offset (00000000) 0Ch **Security_PolicyGroup IntelRsvd** False Factor False Factor False False Factor Facto **Size** 32 bits

24.3.1.5 RTC Oscillator Configuration 0 (OSC1_CFG0)

MEM Offset (00000000) 10h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

24.3.1.6 Peripheral Clock Gate Control (CCU_PERIPH_CLK_GATE_CTL)

24.3.1.7 Peripheral Clock Divider Control 0 (CCU_PERIPH_CLK_DIV_CTL0)

MEM Offset (00000000) 1Ch **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

24.3.1.8 Peripheral Clock Divider Control 1 (CCU_GPIO_DB_CLK_CTL)

MEM Offset (00000000) 20h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

24.3.1.9 External Clock Control Register (CCU_EXT_CLOCK_CTL)

MEM Offset (00000000) 24h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

24.3.1.10 System Low Power Clock Control (CCU_LP_CLK_CTL)

MEM Offset (00000000) 2Ch **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit Size 32 bits

Default 10001_F

Default 0001_F000h

24.3.1.11 Wake Mask register (WAKE_MASK)

Default FFFF_FFFFh

24.3.1.12 AHB Control Register (CCU_MLAYER_AHB_CTL)

MEM Offset (00000000) 34h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

Default 0000_0014h

24.3.1.13 System Clock Control Register (CCU_SYS_CLK_CTL)

False Size 32 bits

24.3.1.14 Clocks Lock Register (OSC_LOCK_0)

MEM Offset (00000000) 3Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

24.3.1.15 SoC Control Register (SOC_CTRL)

False Size 32 bits

24.3.1.16 SoC Control Register Lock (SOC_CTRL_LOCK)

Size 32 bits

24.3.1.17 General Purpose Sticky Register 0 (GPS0)

MEM Offset (00000000) 100h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

24.3.1.18 General Purpose Sticky Register 1 (GPS1)

MEM Offset (00000000) 104h **Security_PolicyGroup IntelRsvd** False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

24.3.1.19 General Purpose Sticky Register 2 (GPS2)

24.3.1.20 General Purpose Sticky Register 3 (GPS3)

24.3.1.21 General Purpose Scratchpad Register 0 (GP0)

24.3.1.22 General Purpose Scratchpad Register 1 (GP1)

MEM Offset (00000000) 118h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0000h

24.3.1.23 General Purpose Scratchpad Register 2 (GP2)

MEM Offset (00000000) 11Ch **Security_PolicyGroup IntelRsvd** False Factor False False Factor False Factor False Factor Factor Factor Factor Factor Factor Factor Factor Factor **Size** 32 bits

24.3.1.24 General Purpose Scratchpad Register 3 (GP3)

MEM Offset (00000000) 120h **Security_PolicyGroup IntelRsvd** False False
Size 32 bit **Size** 32 bits

Default 0000_0000h

24.3.1.25 Write-Once Scratchpad Register (WO_SP)

MEM Offset (00000000) 130h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

0000_0000h

24.3.1.26 Write Once Sticky Register (WO_ST)

MEM Offset (00000000) 134h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

24.3.1.27 Comparator enable (CMP_EN)

24.3.1.28 Comparator reference select (CMP_REF_SEL)

False Size 32 bits

24.3.1.29 Comparator reference polarity select register (CMP_REF_POL)

MEM Offset (00000000) 308h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0000h

24.3.1.30 Comparator power enable register (CMP_PWR)

24.3.1.31 Comparator clear register (CMP_STAT_CLR)

False Size 32 bits **Default** 0000_0000h

System Control Subsystem

System Control Subsystem

24.3.1.32 Host Processor Interrupt Routing Mask 0 (INT_I2C_MST_0_MASK)

24.3.1.33 Host Processor Interrupt Routing Mask 2 (INT_SPI_MST_0_MASK)

MEM Offset (00000000) 454h

Size 32 bits

24.3.1.34 Host Processor Interrupt Routing Mask 4 (INT_SPI_SLV_MASK)

MEM Offset (00000000) 45Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

0001_0001h

24.3.1.35 Host Processor Interrupt Routing Mask 5 (INT_UART_0_MASK)

MEM Offset (00000000) 460h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

0001_0001h

24.3.1.36 Host Processor Interrupt Routing Mask 6 (INT_UART_1_MASK)

MEM Offset (00000000) 464h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

0001_0001h

24.3.1.37 Host Processor Interrupt Routing Mask 8 (INT_GPIO_MASK)

24.3.1.38 Host Processor Interrupt Routing Mask 9 (INT_TIMER_MASK)

False

Size 32 bits **Default** 0001_0001h

24.3.1.39 Host Processor Interrupt Routing Mask 11 (INT_RTC_MASK)

MEM Offset (00000000) 478h **Security_PolicyGroup IntelRsvd** False Factor False Factor False False Factor Facto **Size** 32 bits

0001_0001h

24.3.1.40 Host Processor Interrupt Routing Mask 12 (INT_WATCHDOG_MASK)

MEM Offset (00000000) 47Ch **Security_PolicyGroup IntelRsvd** False False False 32 bit **Size** 32 bits

0001_0001h

24.3.1.41 Host Processor Interrupt Routing Mask 13 (INT_DMA_CHANNEL_0_MASK)

MEM Offset (00000000) 480h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0001_0001h

24.3.1.42 Host Processor Interrupt Routing Mask 14 (INT_DMA_CHANNEL_1_MASK)

24.3.1.43 Host Processor Interrupt Routing Mask 23 (INT_COMPARATORS_HOST_HALT_MASK)

MEM Offset (00000000) 4A8h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Default** 0007_FFFFh

Size 32 bits

24.3.1.44 Host Processor Interrupt Routing Mask 25 (INT_COMPARATORS_HOST_MASK)

False Size 32 bits

24.3.1.45 Host Processor Interrupt Routing Mask 26 (INT_HOST_BUS_ERR_MASK)

MEM Offset (00000000) 4B4h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

0001_0001h

24.3.1.46 Host Processor Interrupt Routing Mask 27 (INT_DMA_ERROR_MASK)

MEM Offset (00000000) 4B8h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

Default 0003_0003h

24.3.1.47 Host Processor Interrupt Routing Mask 28 (INT_SRAM_CONTROLLER_MASK)

MEM Offset (00000000) 4BCh **Security_PolicyGroup IntelRsvd** False False False **Size** 32 bits

0001_0001h

24.3.1.48 Host Processor Interrupt Routing Mask 29 (INT_FLASH_CONTROLLER_0_MASK)

MEM Offset (00000000) 4C0h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

0001_0001h

24.3.1.49 Host Processor Interrupt Routing Mask 31 (INT_AON_TIMER_MASK)

MEM Offset (00000000) 4C8h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

Default 0001_0001h

24.3.1.50 Host Processor Interrupt Routing Mask 32 (INT_ADC_PWR_MASK)

24.3.1.51 Host Processor Interrupt Routing Mask 33 (INT_ADC_CALIB_MASK)

MEM Offset (00000000) 4D0h **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

0001_0001h

24.3.1.52 Interrupt Mask Lock Register (LOCK_INT_MASK_REG)

MEM Offset (00000000) 4D8h **Security_PolicyGroup IntelRsvd** False Factor False Factor False False Factor Facto **Size** 32 bits

0000_0000h

24.3.1.53 AON Voltage Regulator (AON_VR)

System Control Subsystem

24.3.1.54 Power Management Wait (PM_WAIT)

24.3.1.55 Processor Status (P_STS)

False Size 32 bits **Default** 0000_0000h

24.3.1.56 Reset Control (RSTC)

A write to this register with RSTC.COLD or RSTC.WARM set initiates a reset. Software must only write to one of these bits at a time, else the behavior is undefined. These bits automatically clear once the reset occurs, so there is no need for software to clear them.

System Control Subsystem

24.3.1.57 Reset Status (RSTS)

Size 32 bits **Default** 0000_0000h

24.3.1.58 Power Management Lock (PM_LOCK)

False Size 32 bits **Default** 0000_0000h

24.3.1.59 Always on counter register (AONC_CNT)

Default 0000_0000h

24.3.1.60 Always on counter enable (AONC_CFG)

24.3.1.61 Always on periodic timer (AONPT_CNT)

MEM Offset (00000000) 708h **Security_PolicyGroup IntelRsvd** False False False Size 32 bit **Size** 32 bits

Default 0000_0000h

24.3.1.62 Always on periodic timer status register (AONPT_STAT)

MEM Offset (00000000) 70Ch **Security_PolicyGroup IntelRsvd** False **Size** 32 bits

Default 0000_0001h

24.3.1.63 Always on periodic timer control (AONPT_CTRL)

Size 32 bits **Default** 0000_0000h

24.3.1.64 Always on periodic timer configuration register (AONPT_CFG)

MEM Offset (00000000) 714h **Security_PolicyGroup IntelRsvd** False Factor False Factor False False Factor Facto **Size** 32 bits

Default 0000_0000h

24.3.1.65 Peripheral Configuration (PERIPH_CFG0)

24.3.1.66 Configuration Lock (CFG_LOCK)

Size 32 bits

24.3.1.67 Pin Mux Pullup (PMUX_PULLUP)

MEM Offset (00000000) 900h **Security_PolicyGroup IntelRsvd** False Factor False Factor False False Factor Facto **Size** 32 bits

Default 00D0_0000h

24.3.1.68 Pin Mux Slew Rate (PMUX_SLEW)

MEM Offset (00000000) 910h **Security_PolicyGroup IntelRsvd** False False
 Size 32 bit **Size** 32 bits

Default 0000_0000h

24.3.1.69 Pin Mux Input Enable (PMUX_IN_EN)

Size 32 bits **Default** 03FF_FFFFh

24.3.1.70 Pin Mux Select (PMUX_SEL [0..1])

MEM Offset (00000000) [0]:930h [1]:934h **Security_PolicyGroup IntelRsvd** False Factor False **Size** 32 bits

Default 0000_0000h

System Control Subsystem

24.3.1.71 Pin Mux Pullup Lock (PMUX_PULLUP_LOCK)

MEM Offset (00000000) 94Ch **Security_PolicyGroup IntelRsvd** False Factor False Factor False False Factor Facto **Size** 32 bits

Default 0000_0000h

24.3.1.72 Pin Mux Slew Rate Lock (PMUX_SLEW_LOCK)

MEM Offset (00000000) 950h **Security_PolicyGroup IntelRsvd** False Factor Factor False Factor False False Factor Facto **Size** 32 bits

Default 0000_0000h

24.3.1.73 Pin Mux Select Lock 0 (PMUX_SEL_0_LOCK)

False Size 32 bits

System Control Subsystem

24.3.1.74 Pin Mux Slew Rate Lock (PMUX_IN_EN_LOCK)

MEM Offset (00000000) 960h **Security_PolicyGroup IntelRsvd** False Size False Solution of the Same Solutio **Size** 32 bits

Default 0000_0000h

24.3.1.75 Identification Register (ID)

24.3.1.76 Revision Register (REV)

24.3.1.77 Flash Size Register (FS)

24.3.1.78 RAM Size Register (RS)

24.3.1.79 Code OTP Size Register (COTPS)

MEM Offset (00000000) 1010h **Security_PolicyGroup IntelRsvd** False Factor False Factor False False Factor Facto **Size** 32 bits

Default 0000_0008h

24.3.1.80 Data OTP Size Register (DOTPS)

Default 0000_0004h

The SOC supports 2 Always On (AON) counters.

The first counter is an always on free running counter running off the 32kHz RTC clock. The second is a periodic counter which allows a timer value to be loaded, and an interrupt to fire when the timer expires.

25.1 Features

25.1.1 AON Counter

The following is a list of AON counters features:

- A free running up counter running off the 32,768Hz clock
- Can be enabled/disabled via software
- Can be used as a general purpose timer
- Can be used by SW for time-stamping samples received from the sensors/ADC

25.1.2 AON Periodic Timer

The following is a list of AON periodic timer features:

- Periodic counter running off the 32,768Hz clock
- AON Periodic Timer continuously decrements from a configured value
- AON Periodic Timer expires when the counter reaches 0
- When the AON Periodic Timer expires it reloads a configured value and decrements
- The AON Periodic Timer is disabled by loading a value of 0, it is enabled by loading a non 0 value
- Generates an alarm when the timer expires

The AON Control & Status registers are described in the previous chapter on the [System Control Subsystem.](#page-397-0) The AON Periodic Timer configuration comes from the system clock domain – the AON Periodic Timer is clocked using the RTC clock, so it will take a number of core clocks for the AON Periodic Timer configuration to propagate into the RTC clock domain. To program the AON Periodic Timer (i.e. clear an alarm via the AONPT_CTRL.AONPT_CLR register bit or reset the counter value via the AONPT_CTRL.AONPT_RST) the relevant control bit must be set by software and then polled until it is cleared by hardware. At this point the desired configuration has taken effect.

AON Periodic timer runs on RTC Clock. Whenever power is cycled, RTC Oscillator takes time to lock and its lock time $\left($ < 2ms) is typically higher than Hybrid Oscillator $\left($ < 2 us) that provides the system clock. Thus CPU may start to execute much earlier, before RTC oscillator has attained lock. For AON Periodic timer to be started through AONPT_RST=1, RTC Clock has to be running already.

Before setting AONPT_RST register to 1, check if RTC OSC has attained lock and is running. This is achieved by checking for non-zero value of AON Counter, which freeruns on RTC clock if enabled.

The counter can the reset to the value contained in (AONPT_CFG) by writing to 1 to (AONPT_RST). (AONPT_RST) is self-clearing however due to clock domain crossing of register value from the slow to the fast domain, it needs to be polled to ensure the reset has occurred.

- 1. Check if RTC Clock is running by polling for non-zero value on AON Counter. Wait till AON Counter is non-zero (assumption is that AON Counter is already enabled by AONC_CFG. **AONC_CNT_EN = 1**).
- 2. Write the timeout value to (**AONPT_CFG**) to stop the counter
- 3. Write 1 to (**AONPT_RST**) to apply the counter value.
- 4. Poll (**AONPT_RST**) till it clears to 0 to ensure the operation has complete.
- 5. At this time AONPT Counter in RTC Clock domain has started running.

AON Periodic Timer is running in RTC Clock domain. It will take 1 RTC clock cycle to get reflected in AONPT_CNT read data. So AONPT_CNT read data value (in system clock domain) at any time would be 1 RTC clock cycle old value of AONPT counter in RTC clock domain.

Note step (3) can take a number of 32kHz clocks (1000's of 32MHz clocks to complete)

The sequence for clearing an interrupt should be as follows

- 1. Interrupt asserted
- 2. Write 0 to the (AONPT_CFG) to stop the counter
- 3. Write 1 to (AONPT_CLR) to clear the interrupt
- 4. Poll (AONPT_CLR) to ensure the operation has complete

Note step (3) can take a number of 32kHz clocks (1000's of 32MHz clocks to complete)

In addition, if both AON Counter and AON Periodic timer is not used, in order to conserve power, the clocks to these block can be gated by resetting CCU_LP_CLK_CTL.CCU_AON_TMR_CNT_CLK_EN_SW register bit to 0 in SCSS.

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